

DANAE - a new experiment for direct dark matter detection using RNDR DEPFET detectors

Hexi Shi
HEPHY ÖAW

Seminar organized within the project :

*“Hunt for the ‘impossible atoms’:
the quest for a tiny violation of the Pauli Exclusion
Principle. Implications for physics, cosmology
and philosophy,”*

**ID 58158, funded by the John Templeton
Foundation**



DANAE (DANAË)

Direct dArk matter search using DEPFET with repetitive- Non-destructive-readout Application Experiment

OeAW funding for detector technology



“Danae” by G. Klimt

Collaboration

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H. Kluck ^{B,C}, J. Schieck ^{B,C}, H. Shi ^B,



Max-Planck-Gesellschaft Halbleiterlabor, Germany ^A,

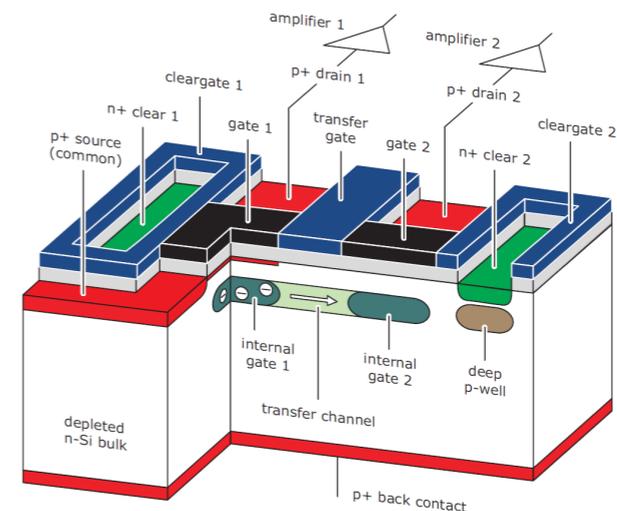
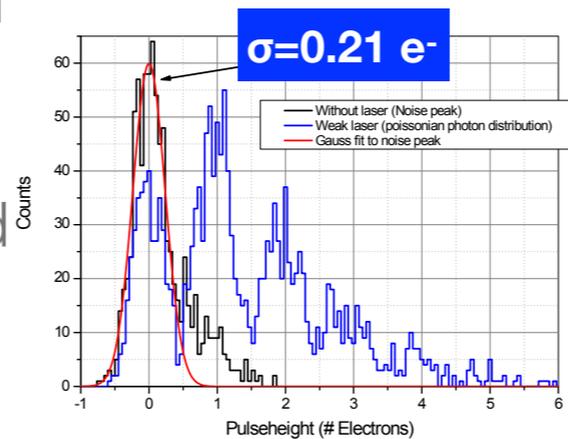
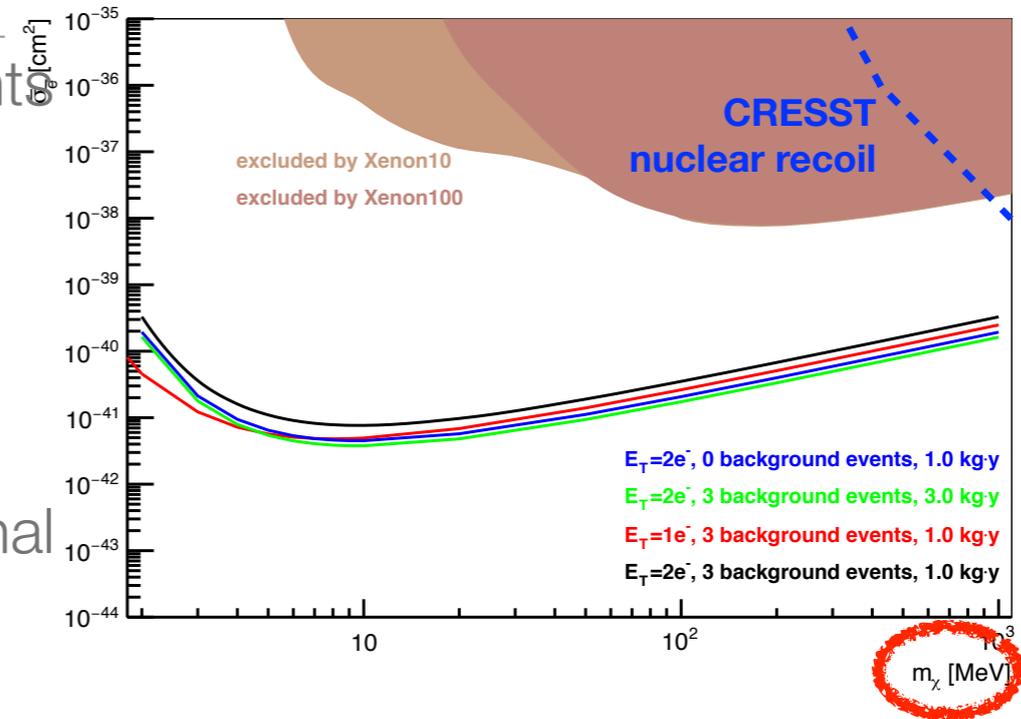
Institut für Hochenergiephysik der Österreichischen Akademie der Wissenschaften, Vienna, Austria ^B,

Atominstytut, Technische Universität Wien, Vienna, Austria ^C

The project overview

Direct Dark Matter Detection with DEPFET

- minimal reach for nuclear recoil experiments about few 100 MeV
- dark matter electron scattering offers **reach towards MeV dark matter**
- measurement of **low noise** ionisation signal in **low background** environment
- RNDR* DEPFET sensors developed by semiconductor laboratory of MPG
- setup for **proof-of-principle measurement** currently prepared
- expect first results early 2019**

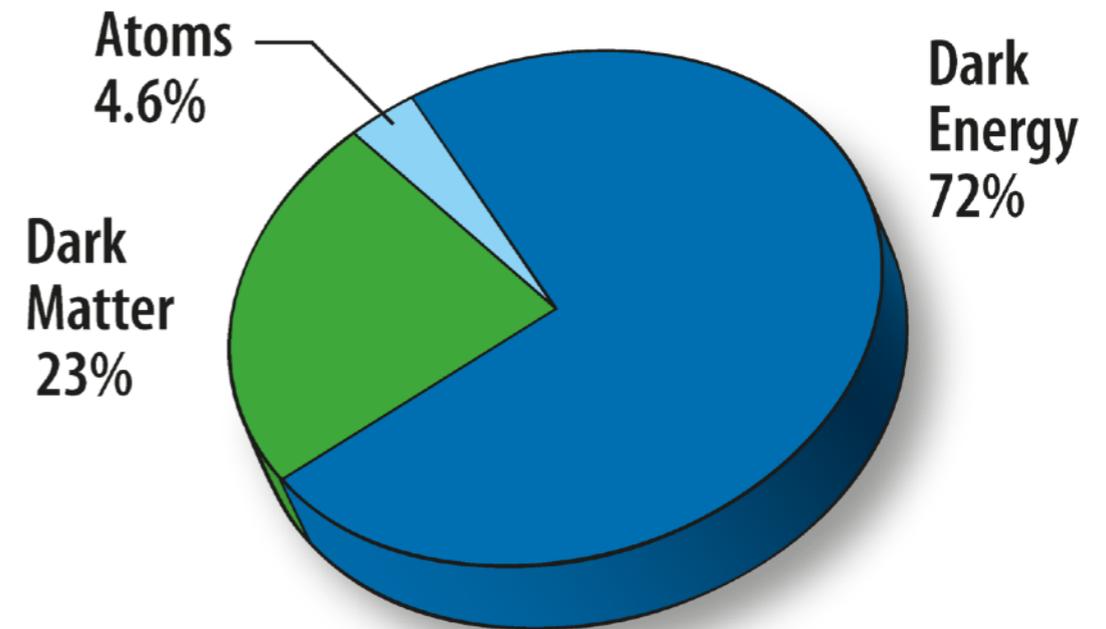


EPJ C, 77(12), 279 (2017)

*Repetitive Non-Destructive Readout

Dark matter landscape - partly

Over 80% of the mass in the universe is invisible dark matter



TODAY

Credit: NASA / WMAP Science Team

“WIMP” as a dark matter candidate :

- weakly interacting with matter

$$\langle \sigma_{\text{WIMP}} \cdot v \rangle \sim G_F^2 \cdot m_X^2 \sim 1/\Omega_X$$

- fits the Hubble constant and “relic” density of dark matter

predicts dark matter WIMP mass between 2 GeV and 120 TeV



WIMPs

dominated the direct detection experiments until recently

WIMP direct detection method

look for nuclear recoils from
WIMP-nucleus scattering

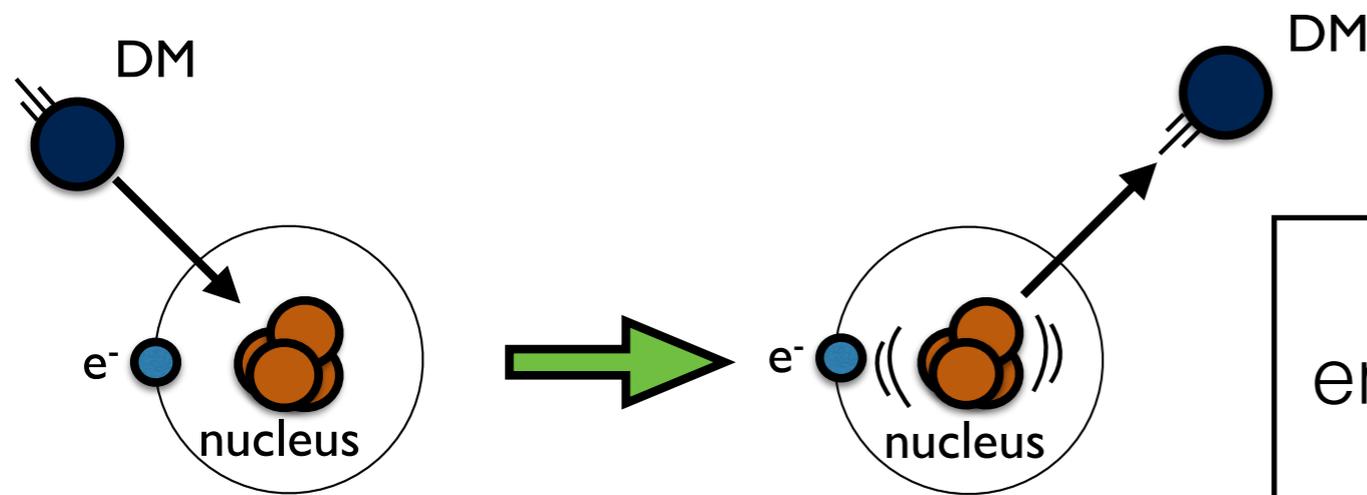


image credit R. Essig

Energy deposit in target
material in forms of :

- light
- phonon
- electric charge

Detection limitation :
energy deposit from nucleus recoil
 $E_{NR} \sim 2\mu_{\chi,N}^2 \cdot v_{\chi}/m_N$

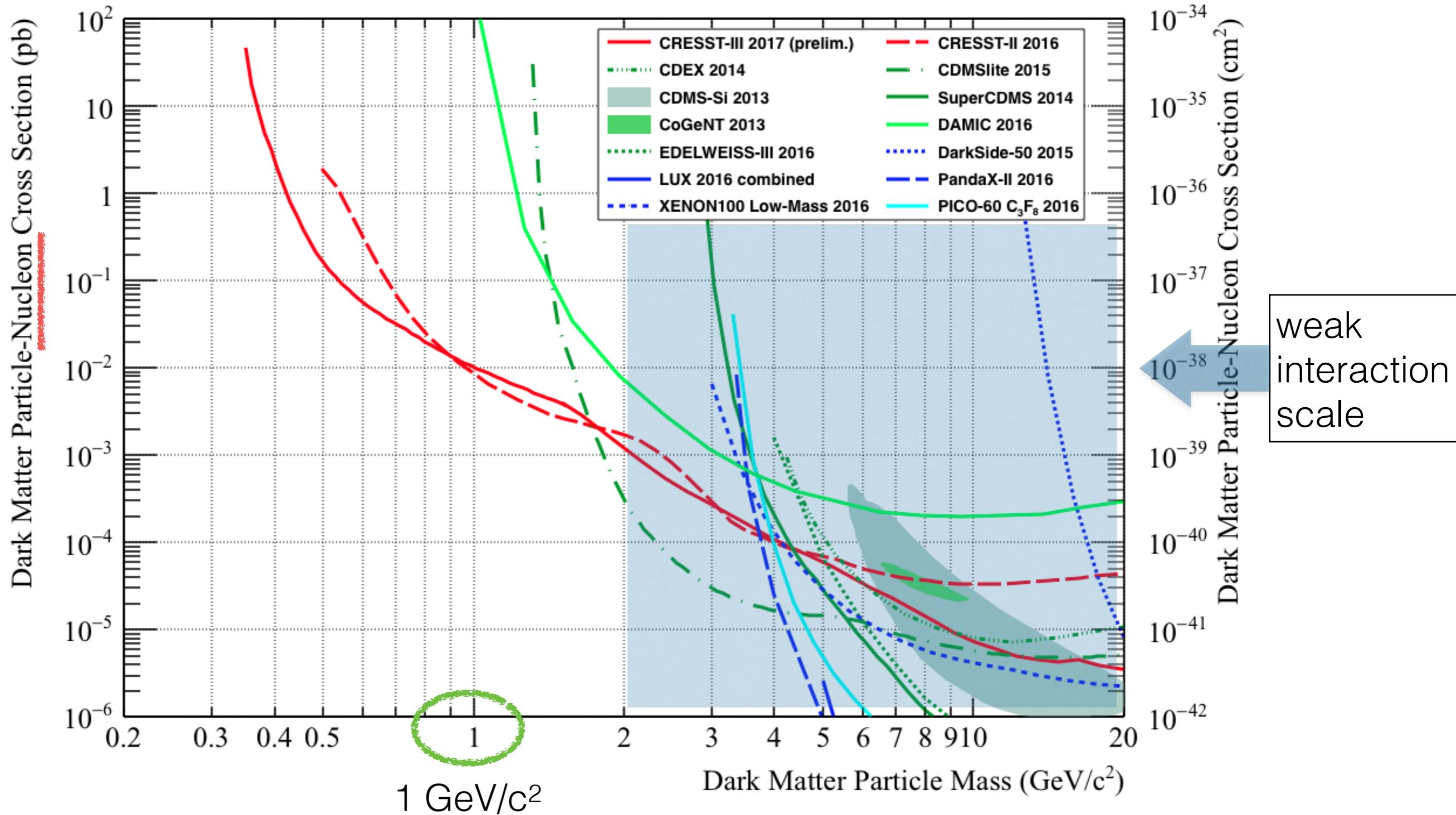
-> for 100 MeV m_{χ} , $E_{NR} \sim 1 \text{ eV}^*$

plus quenching factors and
noise level of the detectors

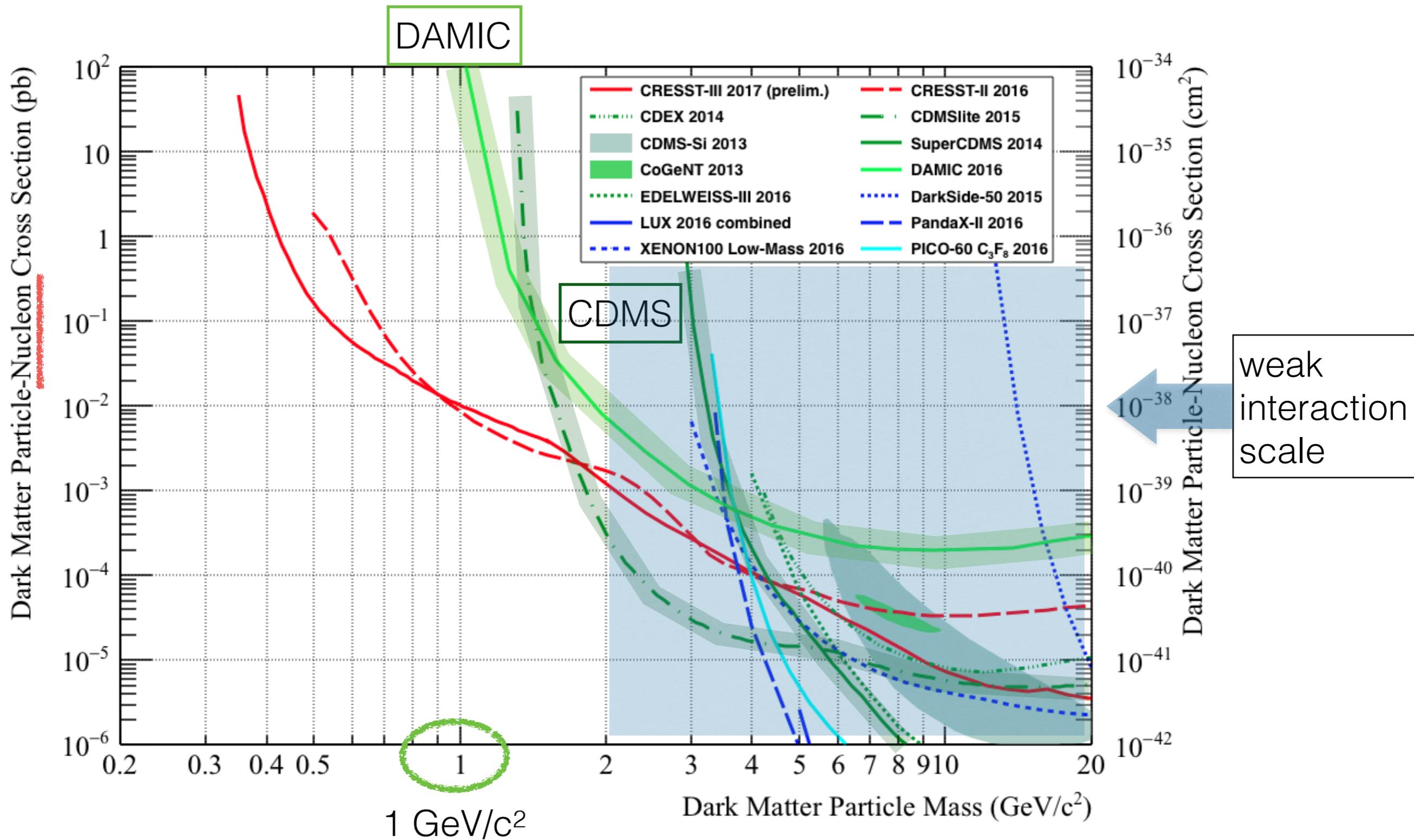
typical DM velocity $v_{\chi} \lesssim 800 \text{ km/s}$

*for silicon

DM-nucleus scattering direct search status



DM-nucleus scattering direct search status



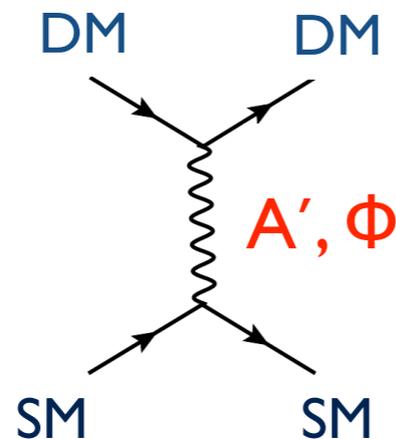
Dark Sector and Light Dark Matter



Dark sectors
(DM + new mediators)

WIMPs

several sharp “theory” targets
(freeze-out, asymmetric, freeze-in, SIMP, ELDER)



DM scattering

Dark sector :
interaction between DM and
standard model particle
mediated by a dark photon
(one example of mediators)

clear predictions from
multiple models over wide
DM mass region, including
keV ~ GeV range
-> comparable observables
in experiments

image credit R. Essig

DM-electron scattering

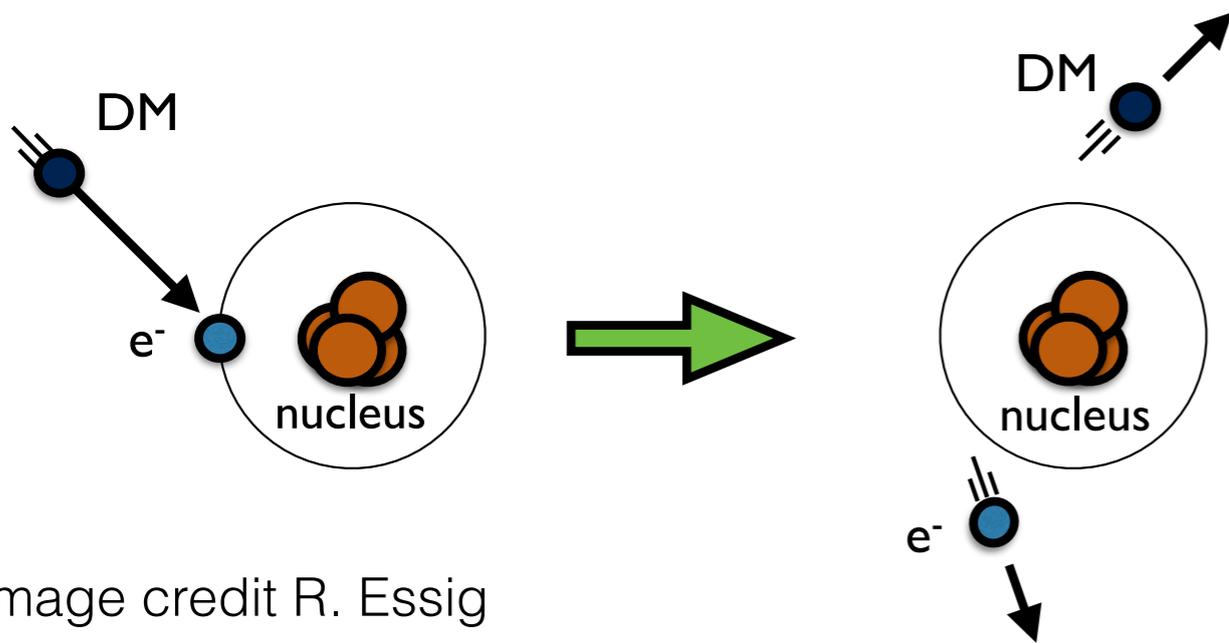


image credit R. Essig

kinematically

to overcome binding energy ΔE

$$\text{need } E_{\text{DM}} \sim \frac{1}{2} m_{\text{DM}} v_{\text{DM}}^2 > \Delta E$$

$$v_{\text{DM}} \lesssim 800 \text{ km/s} \implies m_{\text{DM}} \gtrsim 300 \text{ keV} \left(\frac{\Delta E}{1 \text{ eV}} \right)$$

O(100 keV)

DM-electron scattering

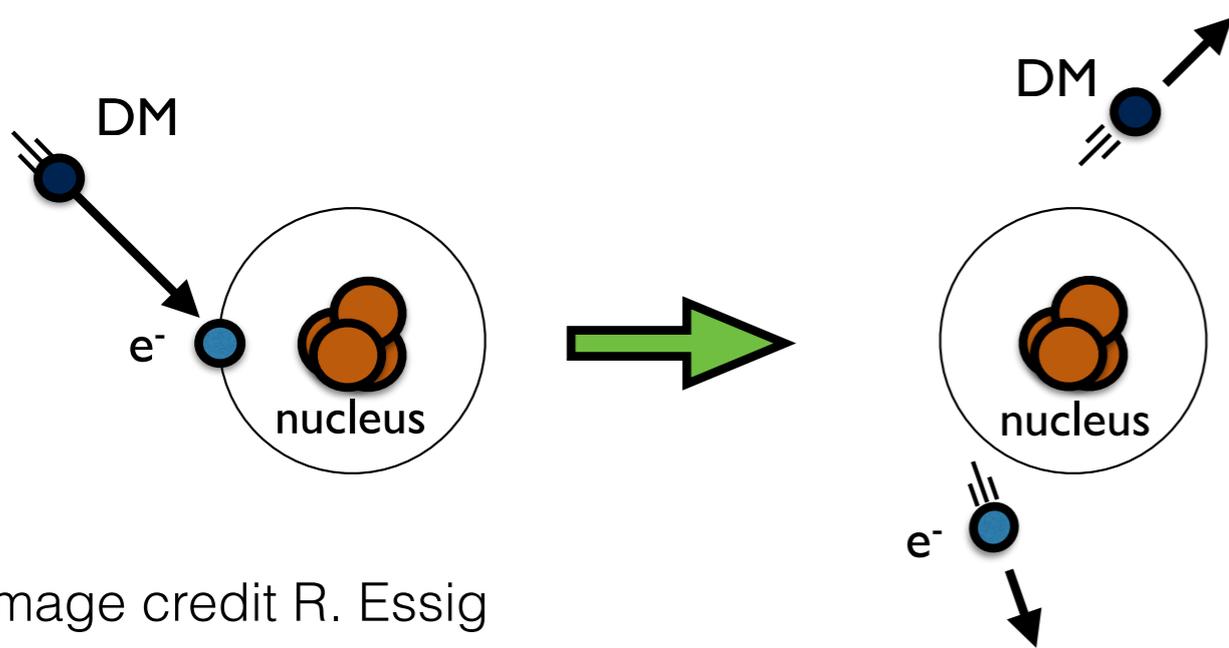


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O(100 keV)

bound e^- does not have definite momentum,
typical momentum transfer is set by e^- not by DM.

$$q_{\text{typ}} \sim \alpha m_e \sim 4 \text{ keV}$$

(for outer shell electron)

$$\text{transferred energy: } \Delta E_e \sim \vec{q} \cdot \vec{v}_{\text{DM}}$$

$$\Delta E_e \sim 4 \text{ eV}$$

typical
recoil energy

Target materials for electron recoils

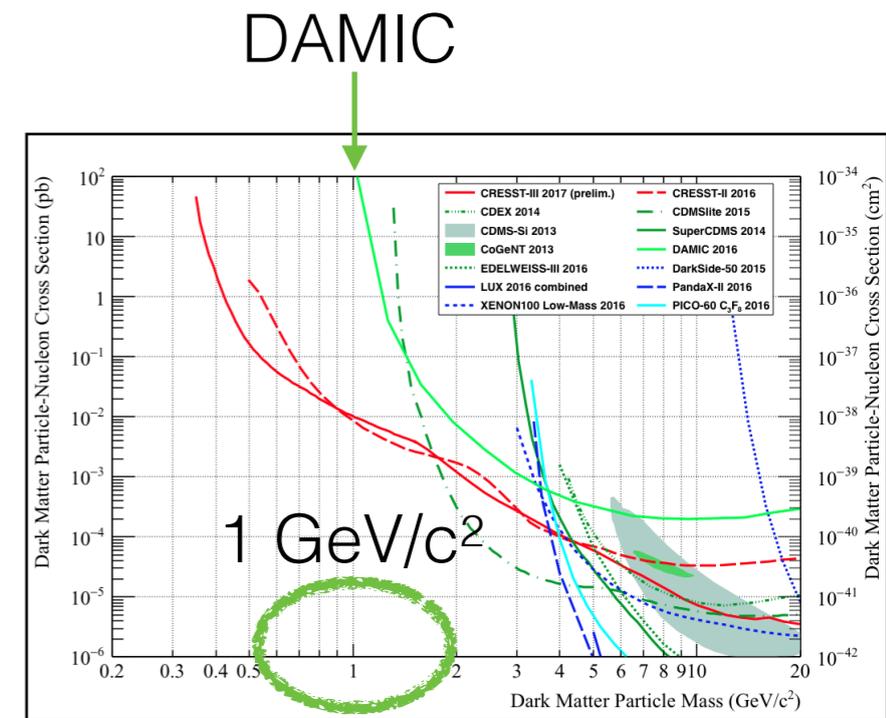
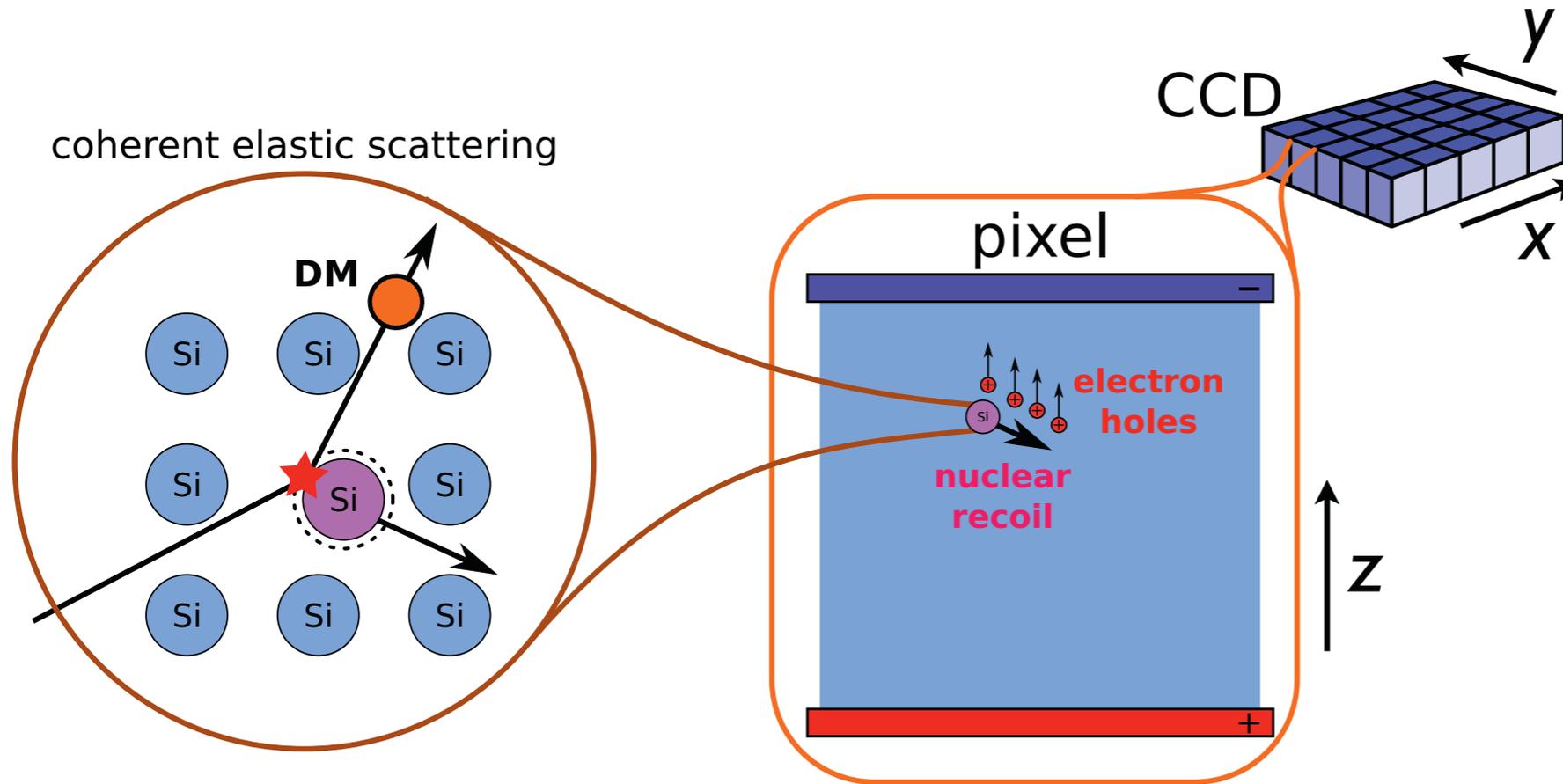
Target Type	Examples	E_{th}	m_χ threshold	Status	Timescale
Noble liquids	Xe, Ar, He	~ 10 eV	~ 5 MeV	Done w data; improvements possible	existing
Semi-conductors	Ge, Si	~ 1 eV	~ 200 keV	($E_{\text{th}} \sim 40$ eV SuperCDMS, DAMIC) $E_{\text{th}} \sim 1$ eV SENSEI , DEPFET R&D	~ 1 -2 years
Scintillators	GaAs, NaI, CsI, ...	~ 1 eV	~ 200 keV	R&D required	≤ 5 years
Superfluid	He	~ 1 eV	~ 1 MeV	R&D required unknown background	≤ 5 years
Super-conductor	Al	~ 1 meV	~ 1 keV	R&D required unknown background	$\sim 10 - 15$ years

arXiv:1608.08632

Application of Silicon detector

DAMIC

nucleus recoil CCD, with physics results



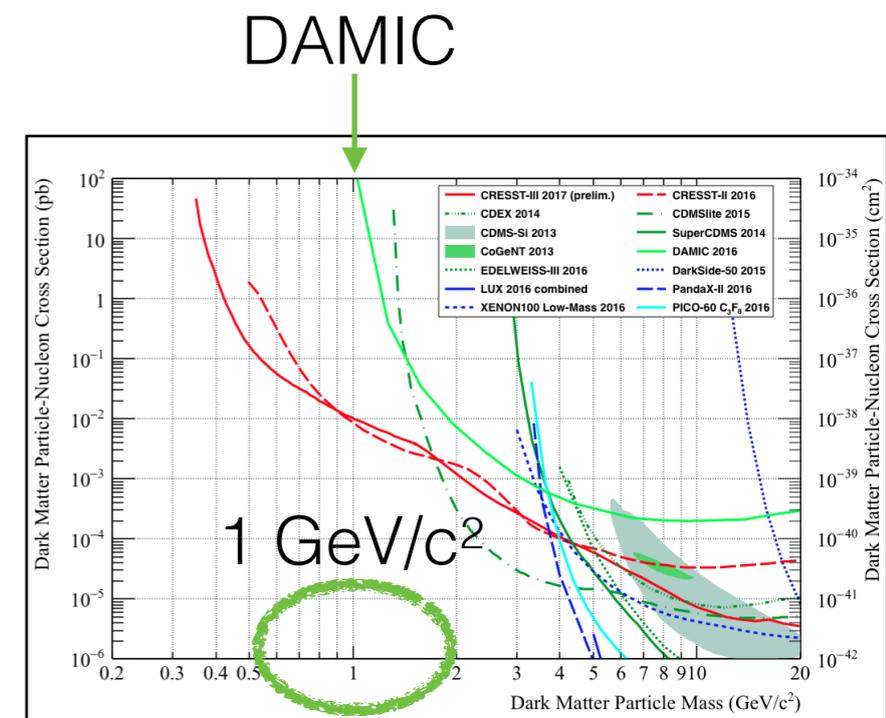
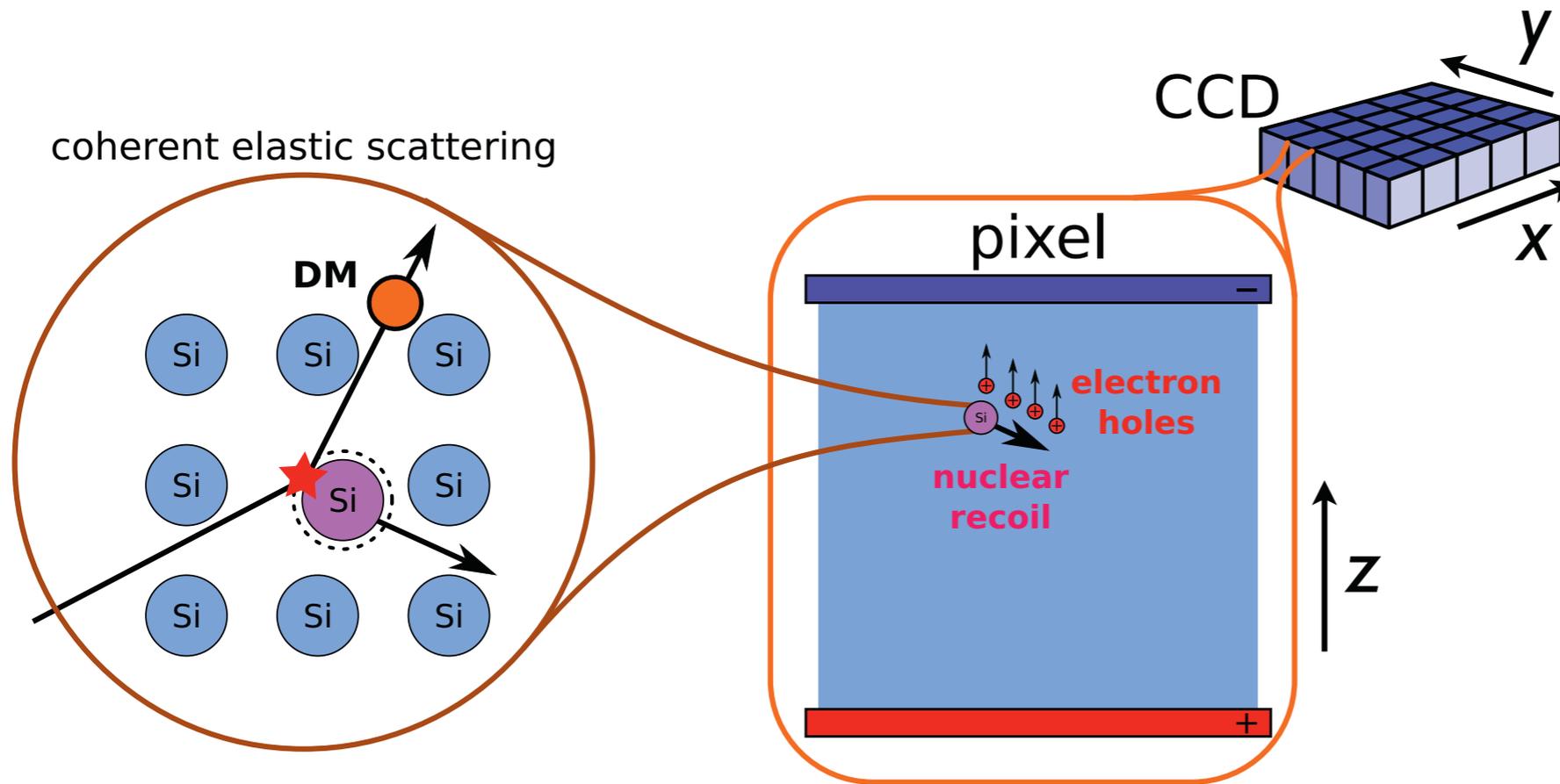
Physics Procedia 61 (2015) 21 – 33

Readout noise determines threshold of $\sim 11 e^-$
(or $\sim 40 eV$)

Application of Silicon detector

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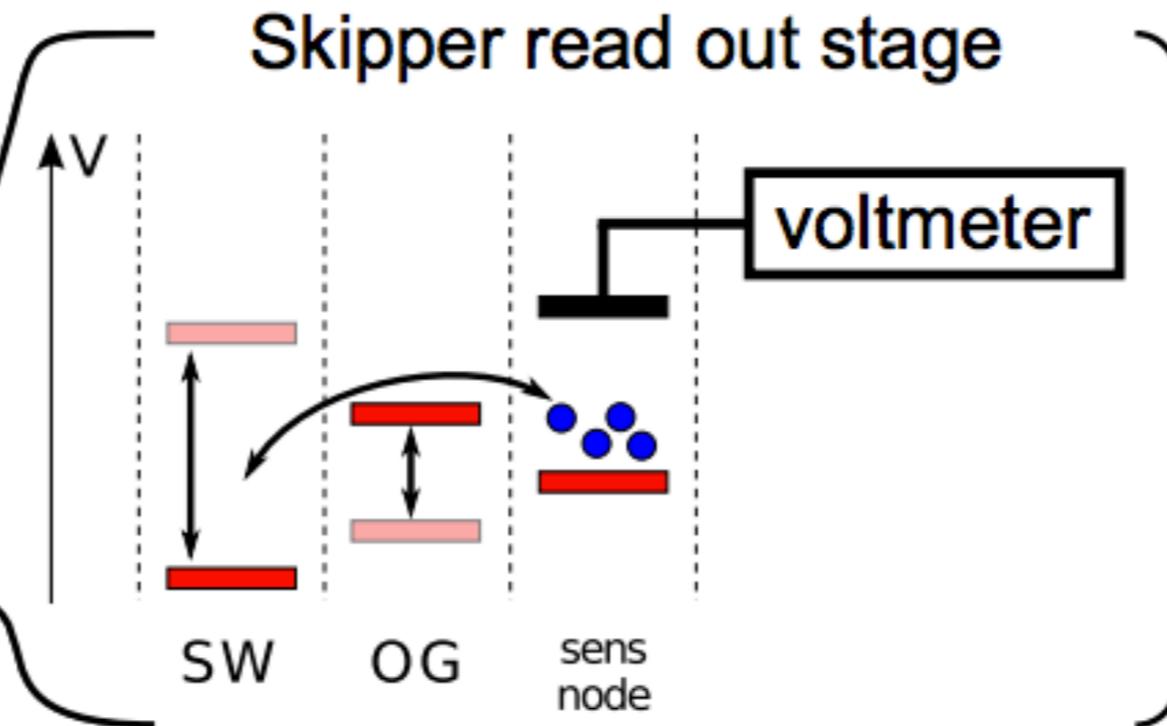
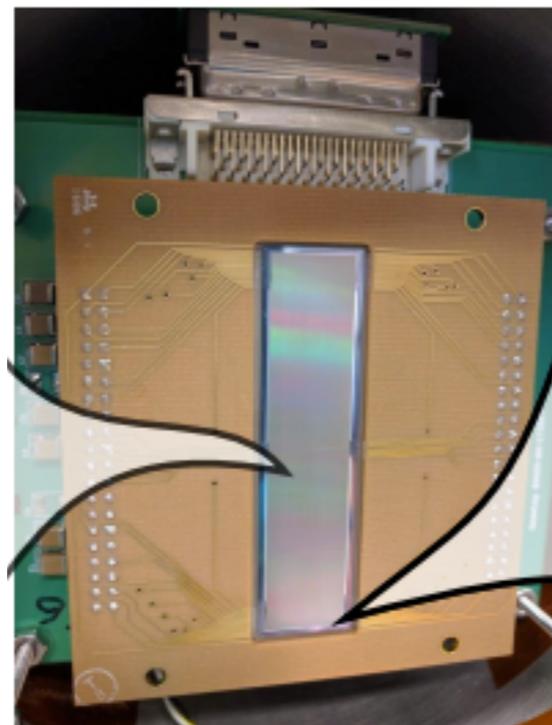


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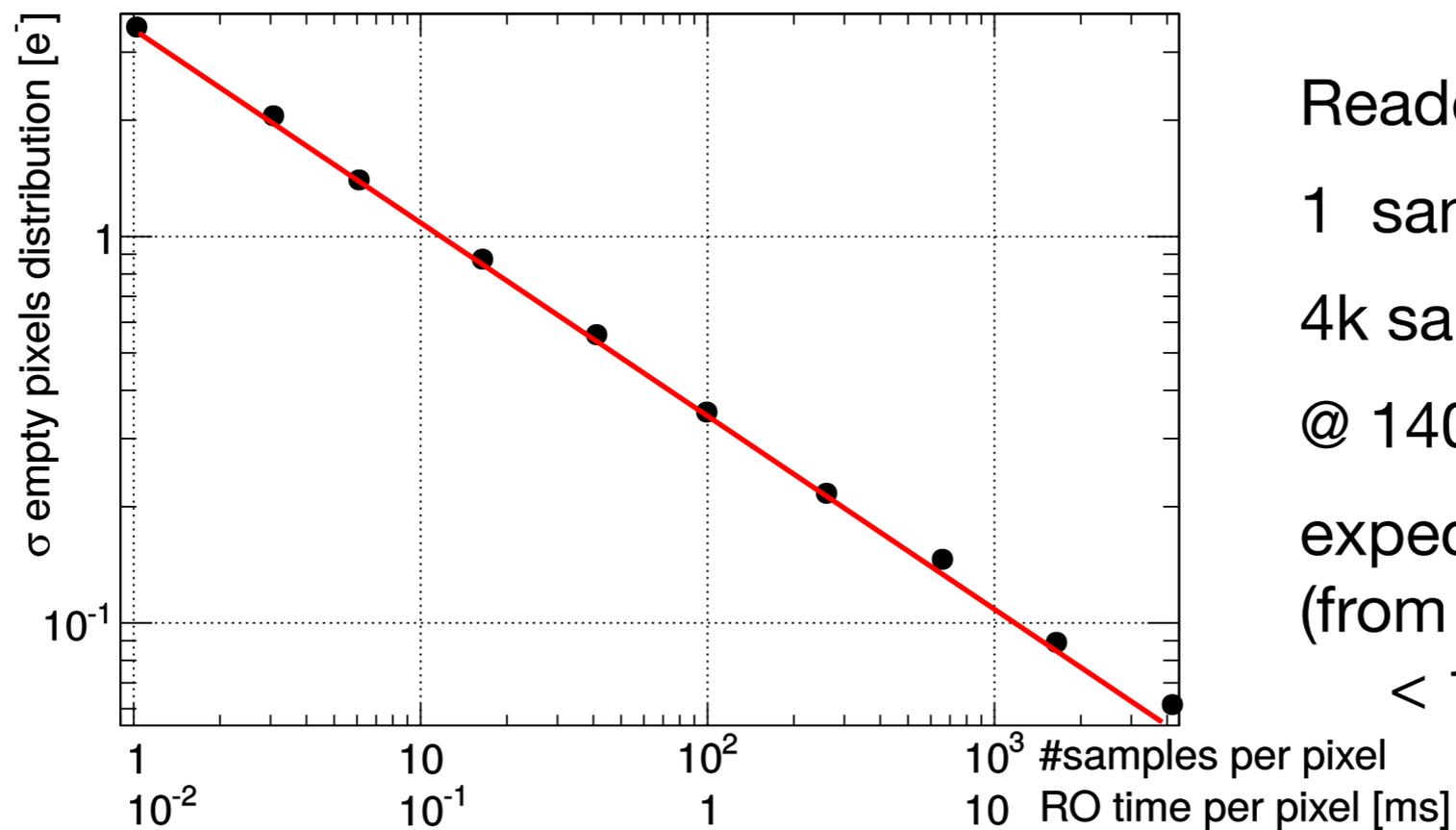
For $O(\text{MeV})$ DM-electron scattering, required threshold : $O(e^-)$
Sub-electron noise level necessary

Skipper CCD for SENSEI

DAMIC CCD with repetitive readout



from SENSEI homepage



Readout noise :

1 sample : 3.55 e⁻ rms

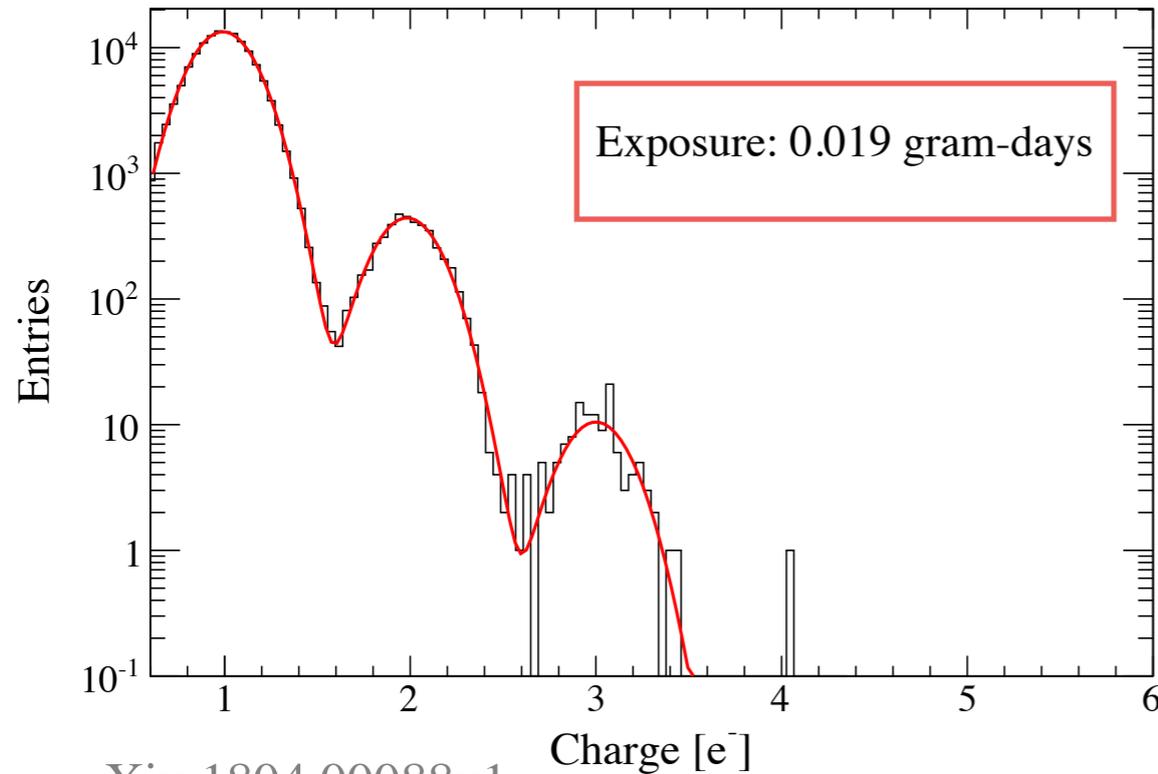
4k samples : 0.068 e⁻ rms

@ 140 K

expected dark current
(from DAMIC CCD) :

< 10⁻³ e⁻/pix/day

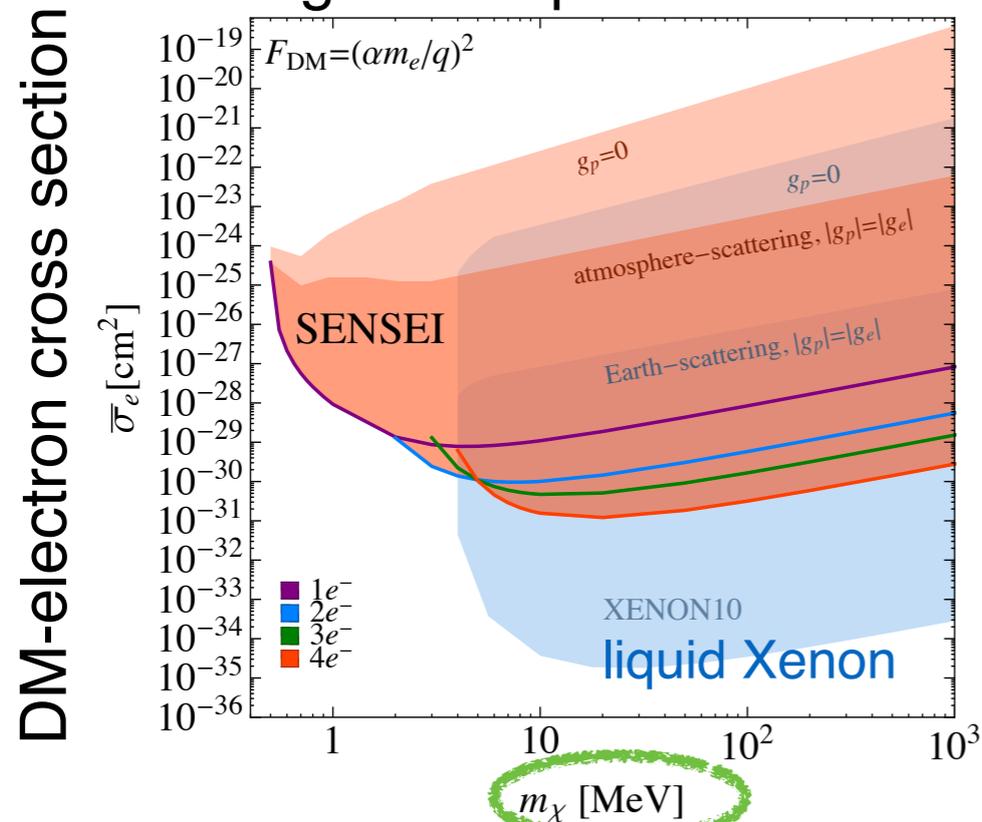
SENSEI first result from a surface run



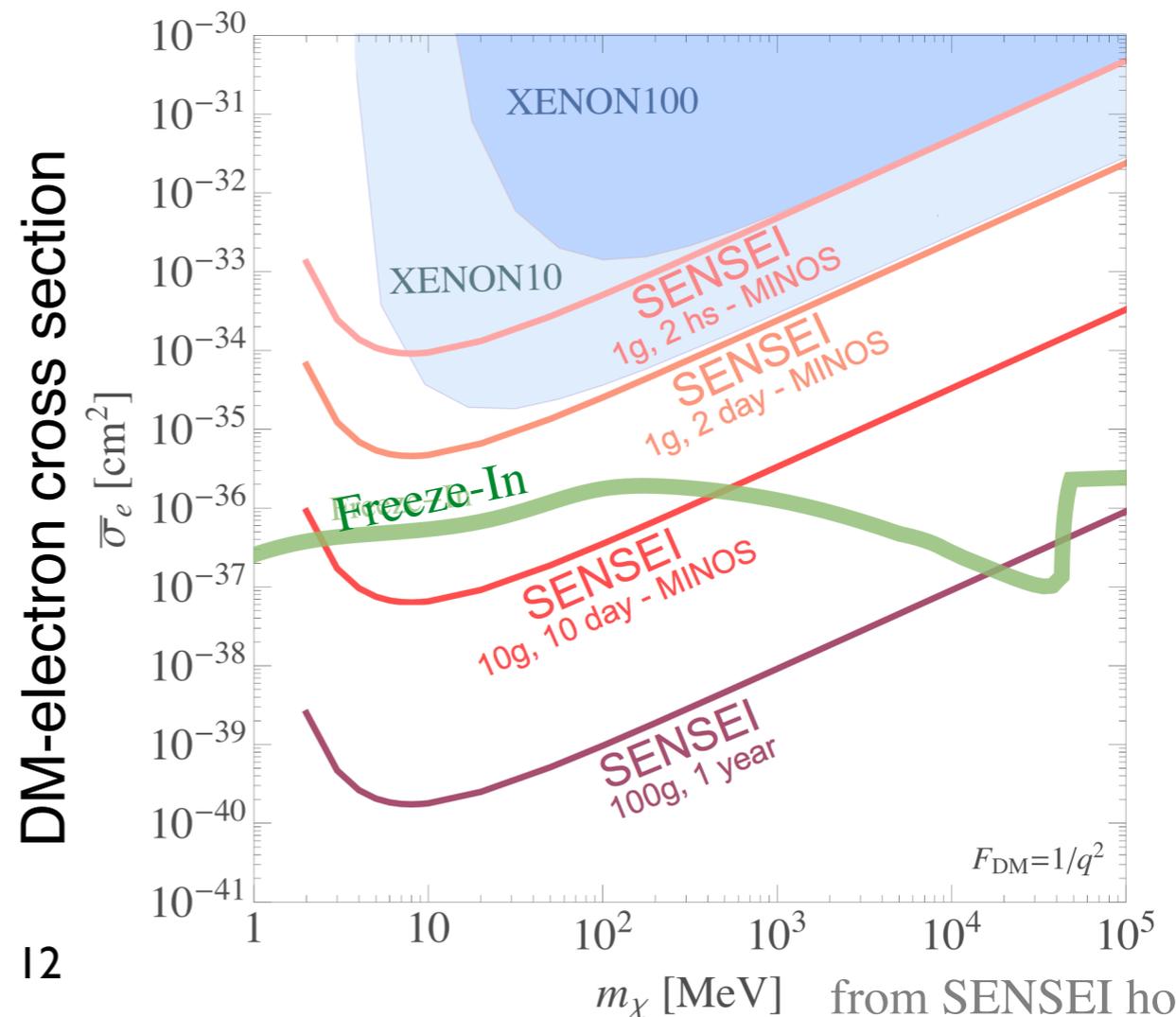
arXiv:1804.00088v1

Active mass : 0.071 grams
 427 minutes exposure (0.33 g-hr)
 above sea level 220 m
 single read noise : $\sim 4 e^-$
effective noise : $\sim 0.14 e^-$ (800 repetitions)
dark current : $\sim 1.14 e^-/\text{pixel}/\text{day}$
 assume all events DM induced
 -> conservative limit

ultralight dark photon mediator



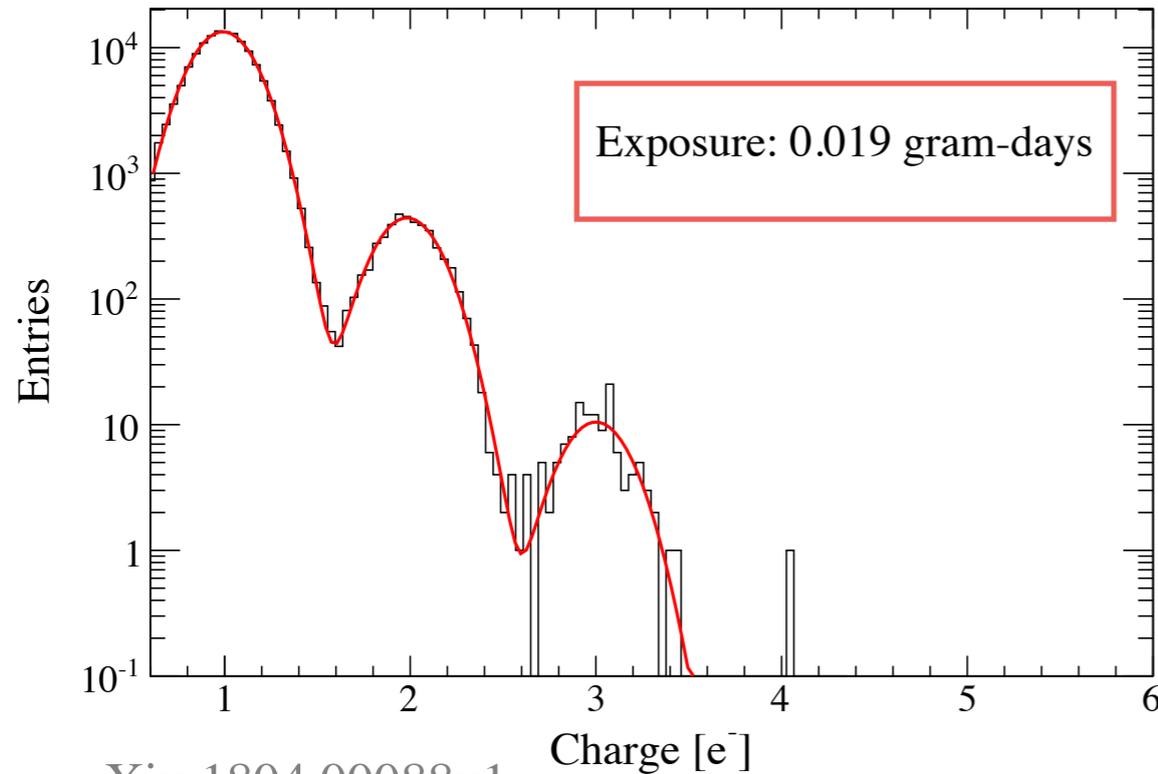
arXiv:1804.00088v1



12

from SENSEI homepage

SENSEI first result from a surface run

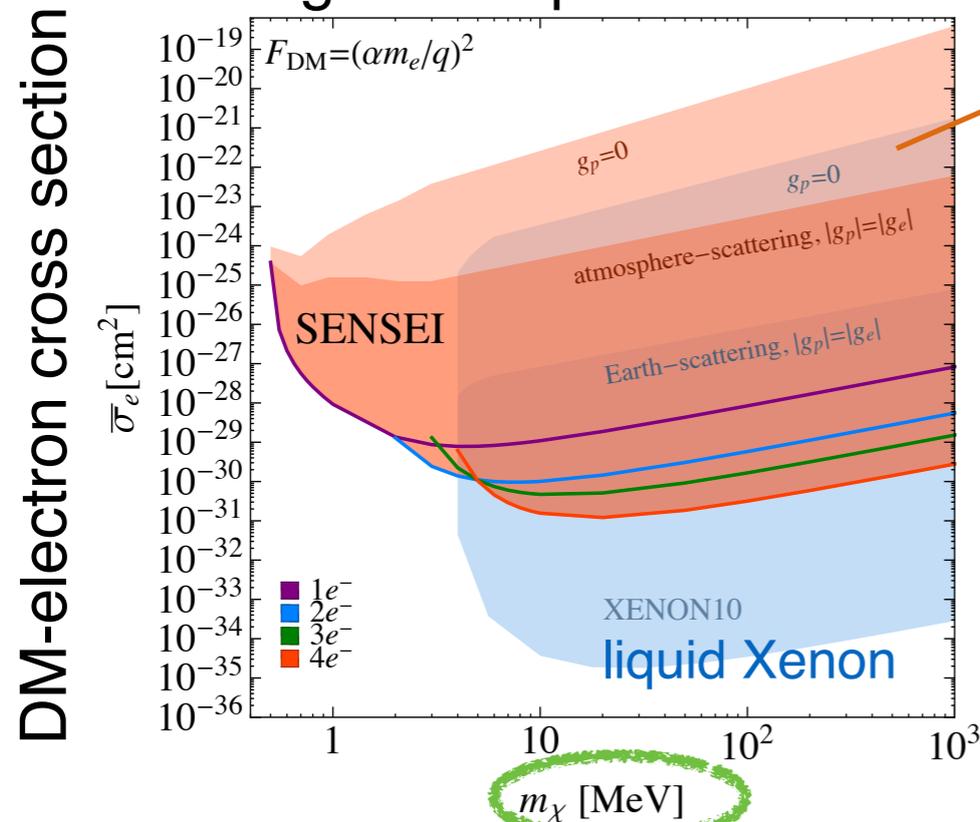


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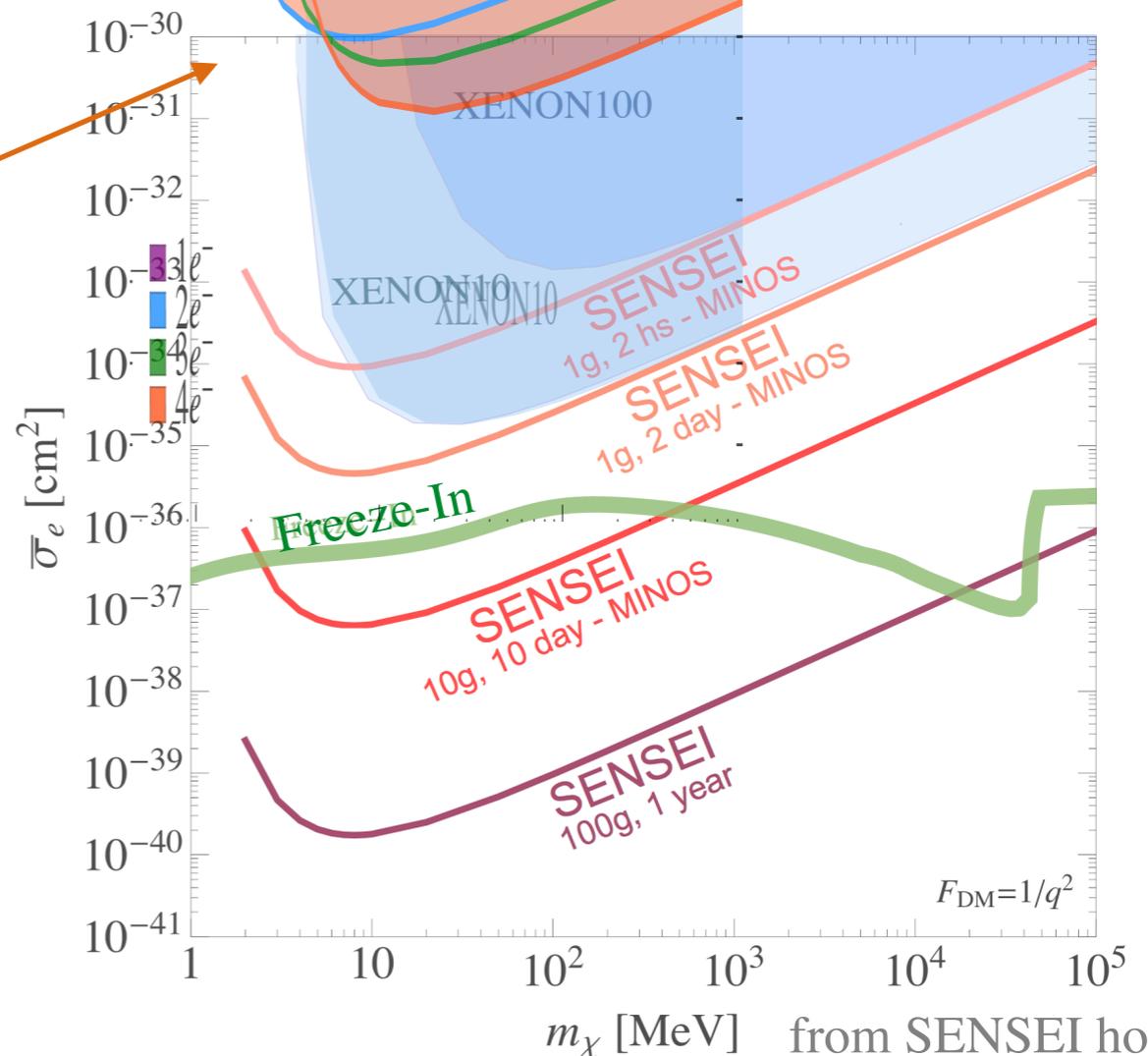
-> conservative limit

ultralight dark photon mediator



arXiv:1804.00088v1

DM-electron cross section



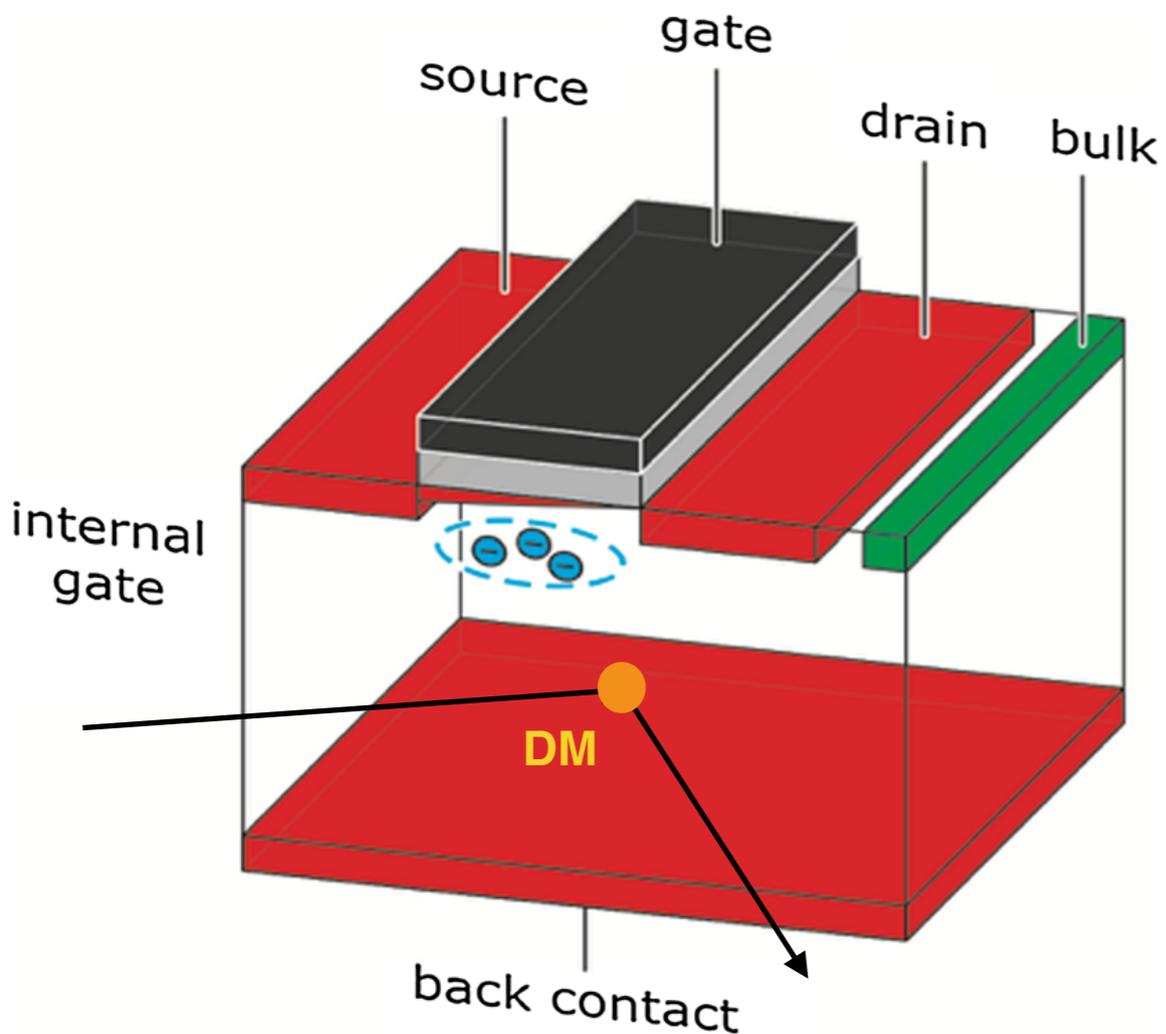
12

from SENSEI homepage

DEPFET with RNDR

RNDR : repetitive non-destructive readout

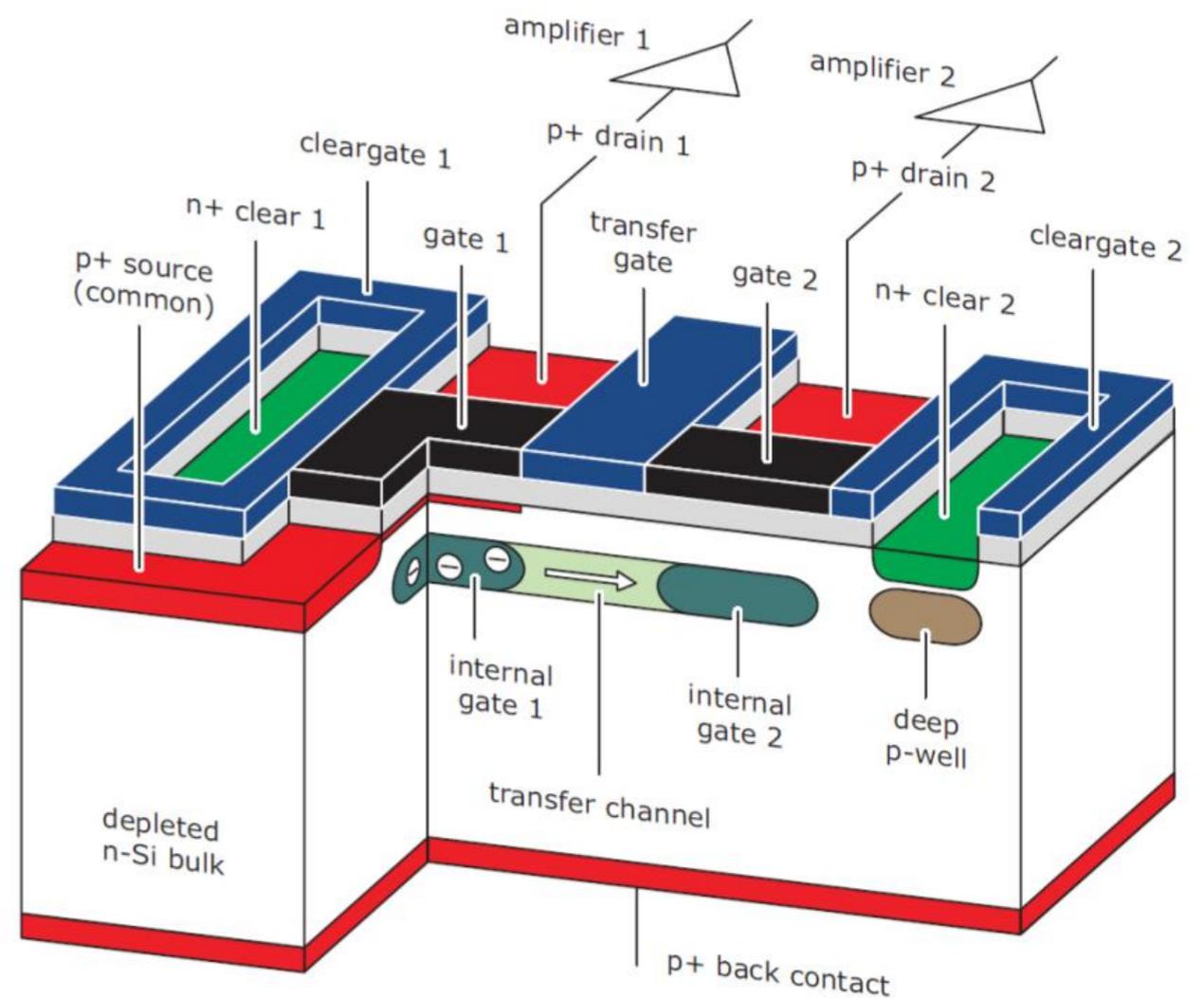
structure of a basic DEPFET cell :
a “subpixel”



EPJ C, 77(12), 279 (2017)

fully-depleted n-Si

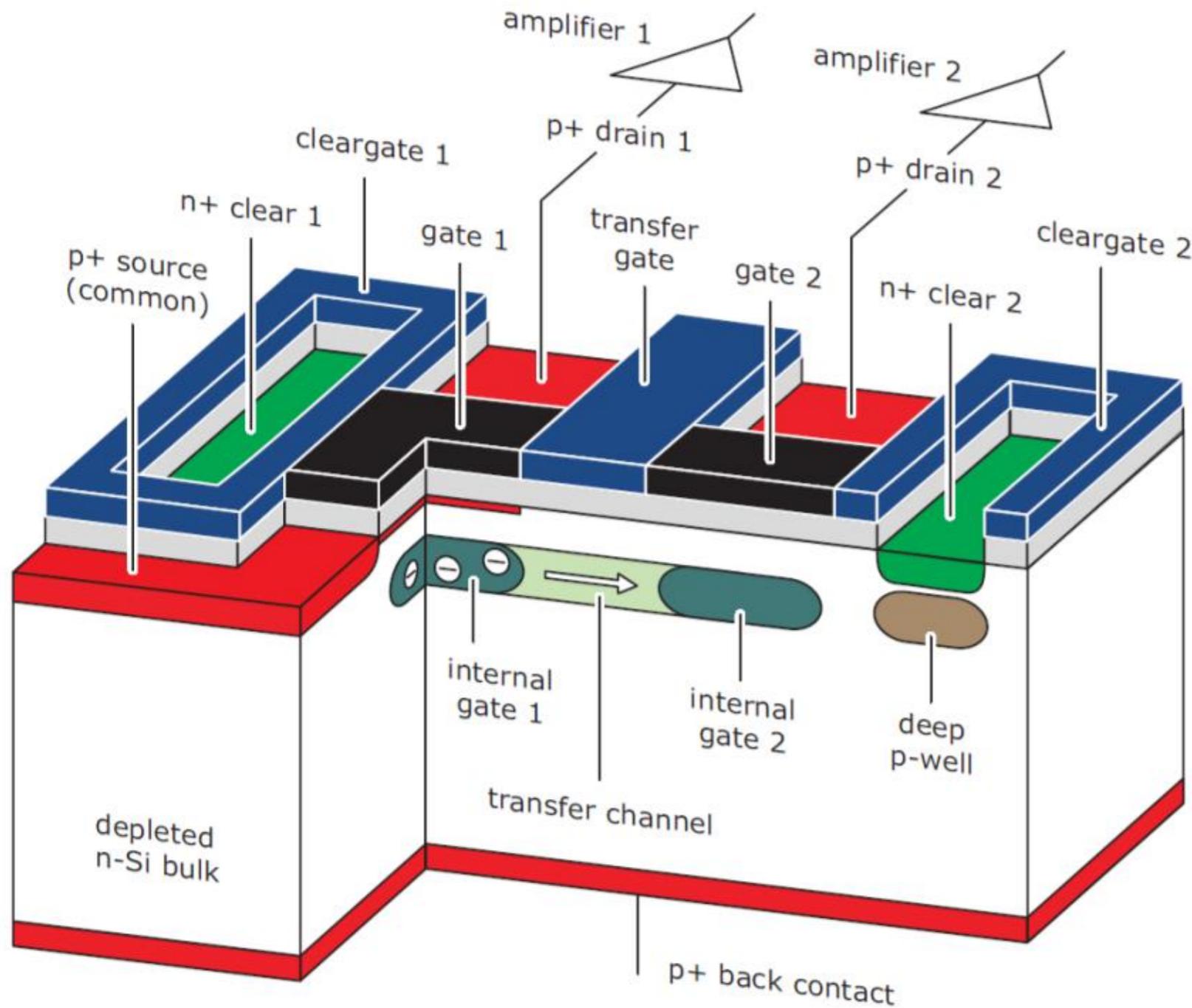
structure of RNDR DEPFET “super-pixel”



EPJ C, 77(12), 279 (2017)

RNDR

RNDR readout

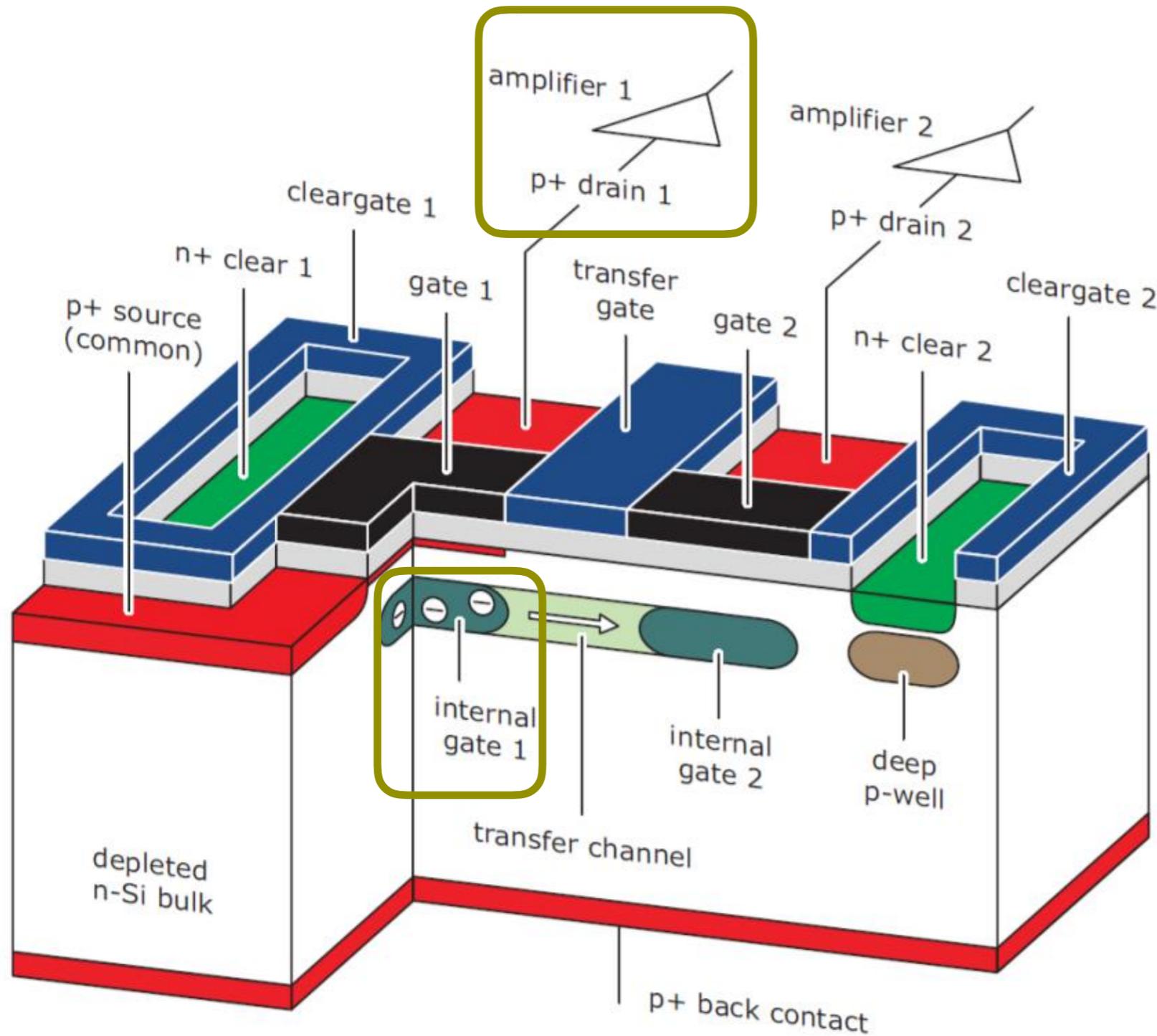


EPJ C, 77(12), 279 (2017)

read N times effective noise :

$$\sigma_{\text{eff}} = \sigma / (\sqrt{N})$$

RNDR



RNDR readout

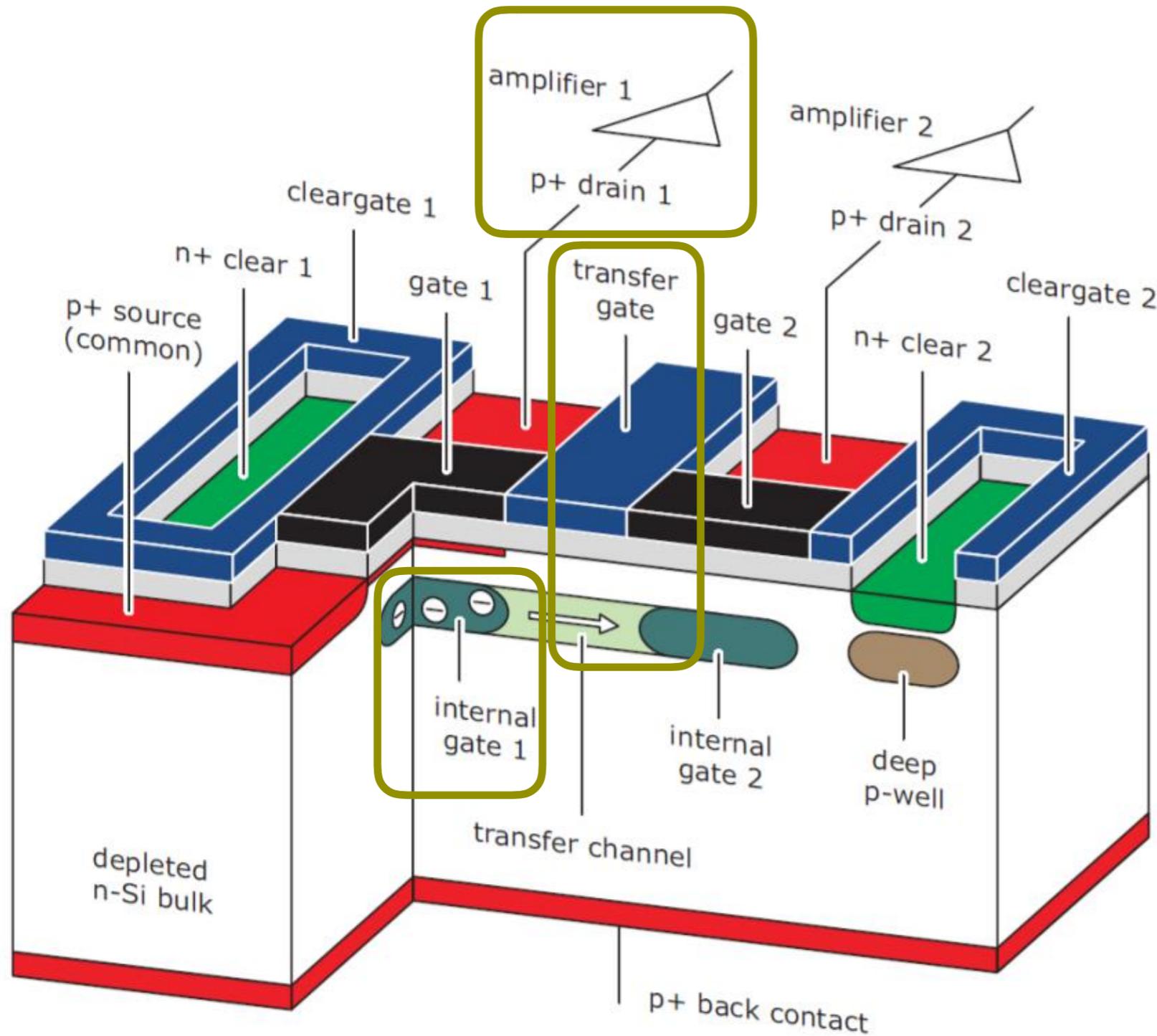
read **1** : noise σ

EPJ C, 77(12), 279 (2017)

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RNDR



RNDR readout

read **1** : noise σ



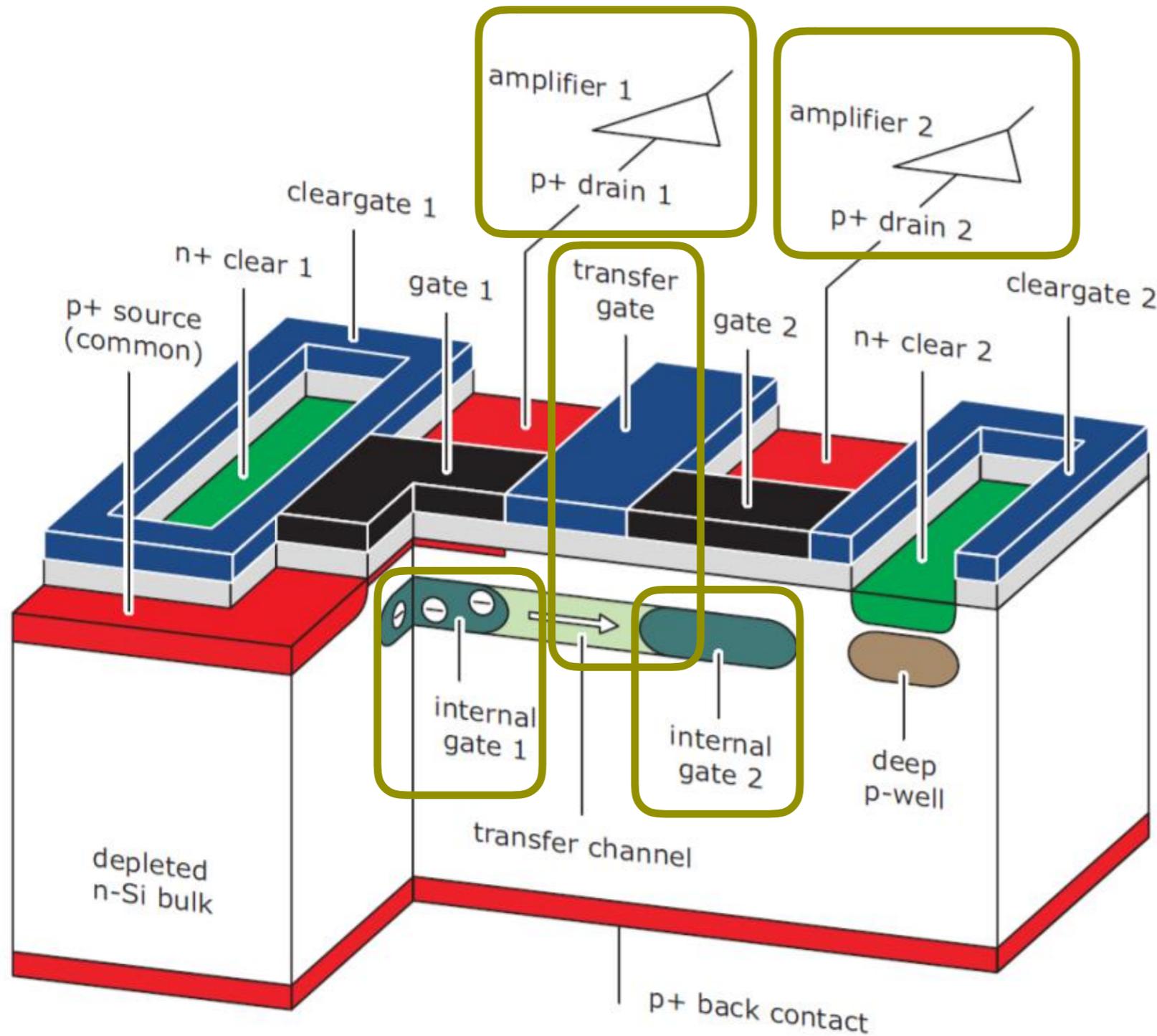
transfer gate open

EPJ C, 77(12), 279 (2017)

read N times effective noise :

$$\sigma_{\text{eff}} = \sigma / (\sqrt{N})$$

RNDR



EPJ C, 77(12), 279 (2017)

RNDR readout

read **1** : noise σ



transfer gate open

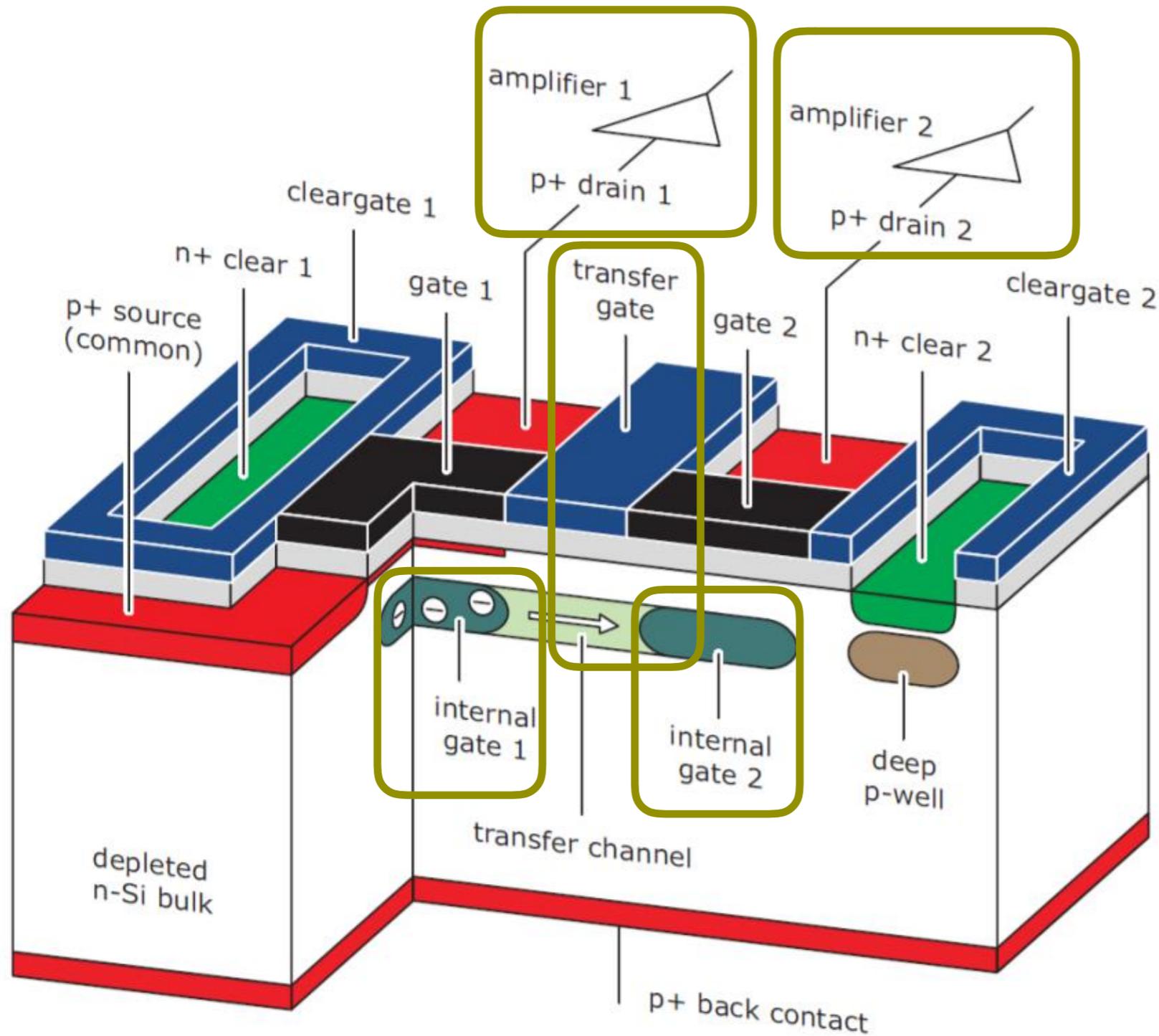


read **2** : noise σ

read N times effective noise :

$$\sigma_{\text{eff}} = \sigma / (\sqrt{N})$$

RNDR



EPJ C, 77(12), 279 (2017)

RNDR readout

read **1** : noise σ



transfer gate open



read **2** : noise σ

: repeat **N** times
independent
measurements



clear charges

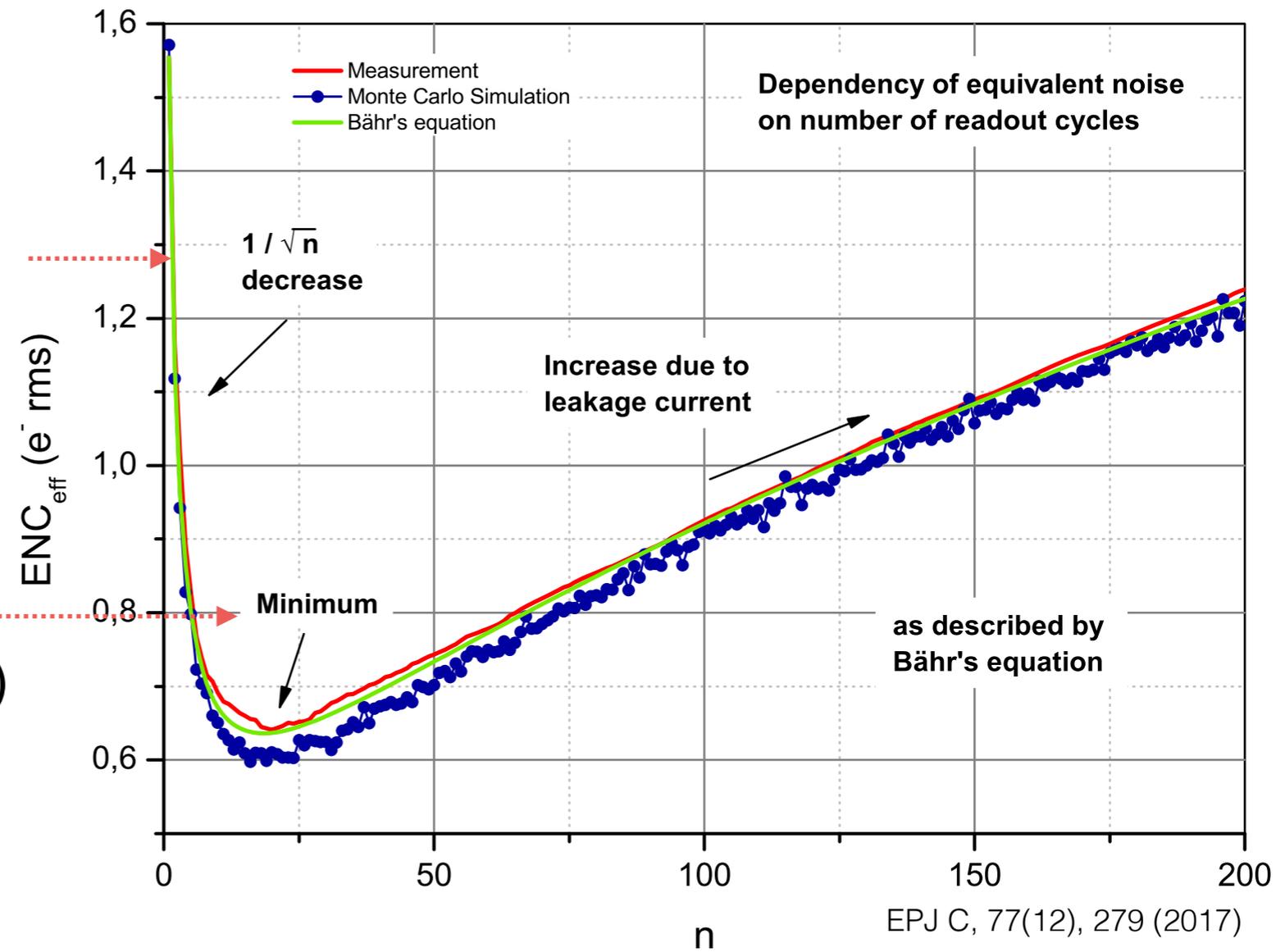
read N times effective noise :

$$\sigma_{\text{eff}} = \sigma / (\sqrt{N})$$

DEPFET RNDR single pixel performance

confirmed the $1/\sqrt{N}$ decrease of σ_{eff}

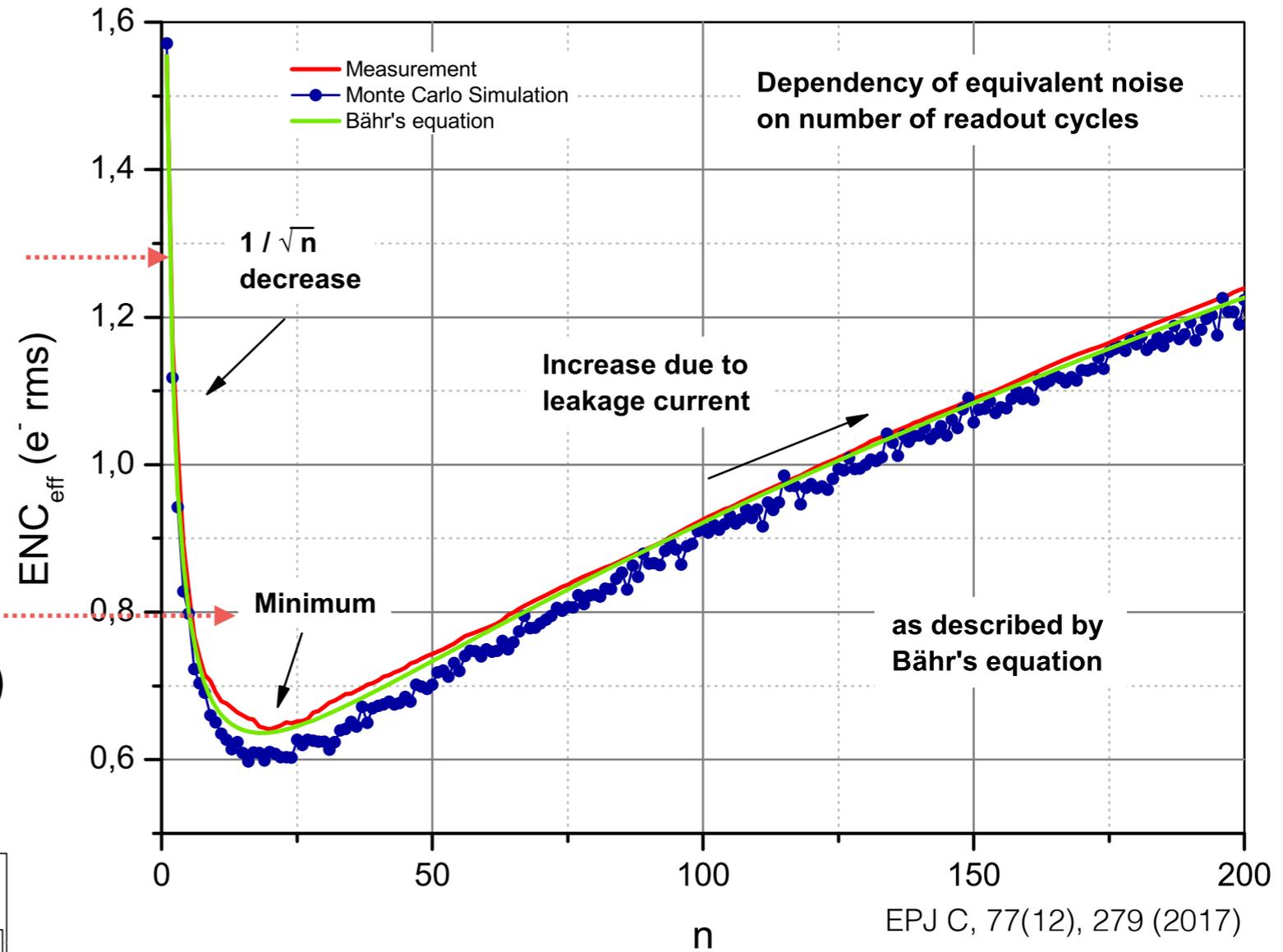
minimal noise level limited by leakage current at 230 K (-40 °C)



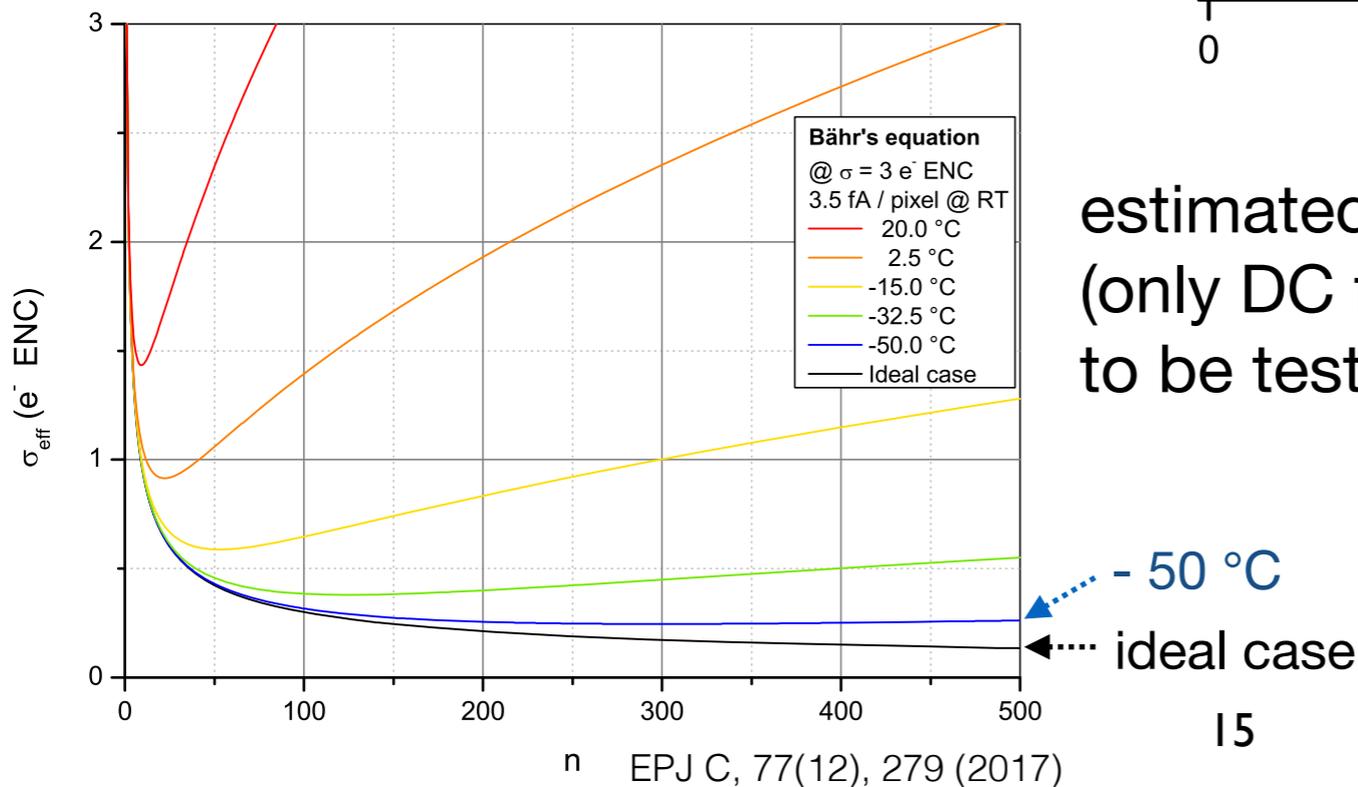
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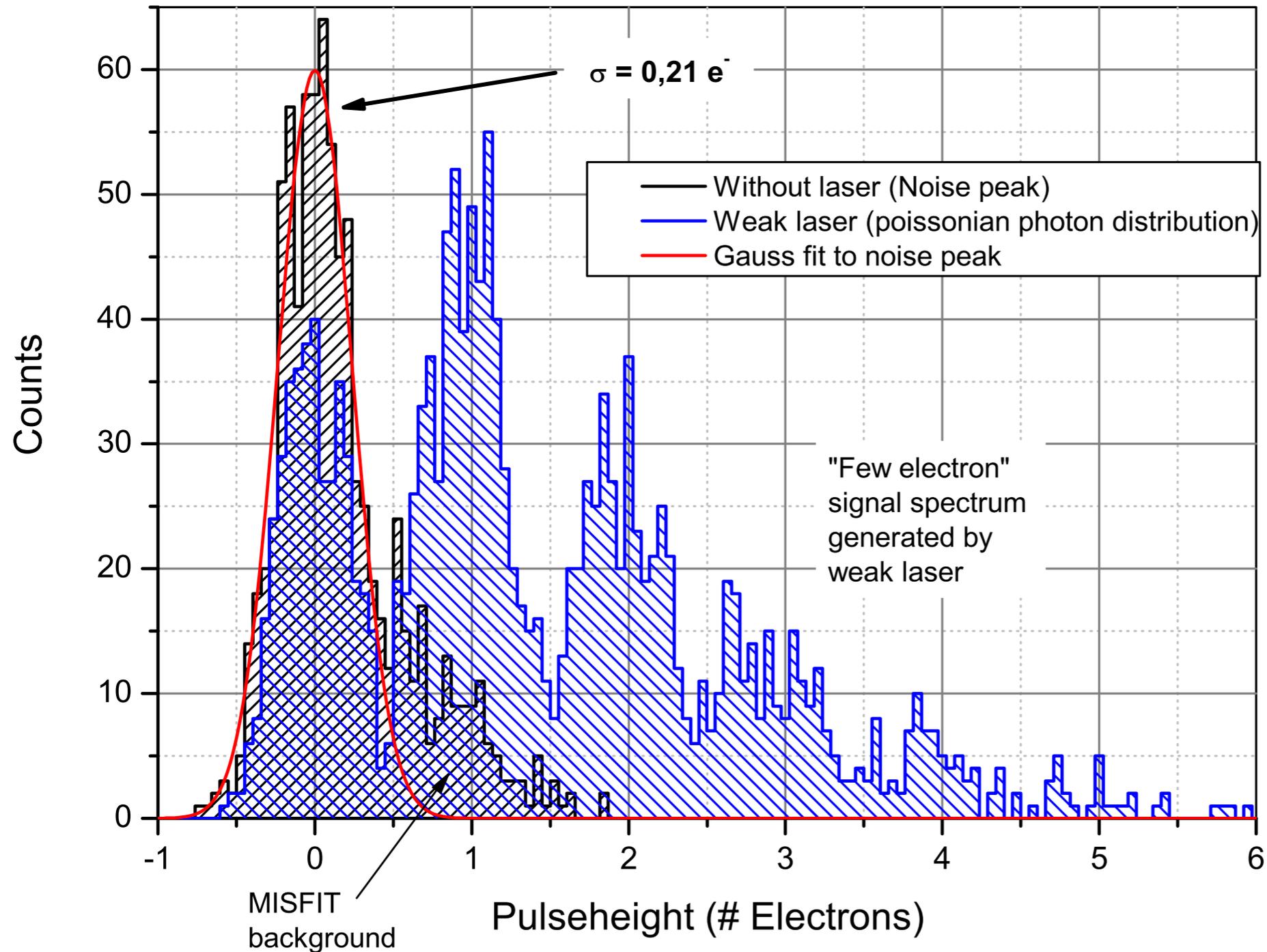


estimated temperature dependence (only DC from thermal excitation) to be testified in measurement



new architecture with "blind-gate" possibility of reducing leakage current during readout

DEPFET RNDR single pixel performance



single pixel RNDR
DEPFET effective noise :
0.2 e⁻ RMS at 200 K

capable of distinguish
single electron charge

A comparison with skipper CCD

Type	Pixel format [μm]	prototype mass	operating temp	dark current	readout time (1 sample)	readout noise (optimal)
skipper CCD	15 x 15 x 200	0.071 g	140 K	<u>~1.14</u> e ⁻ /pix/day	10 μs/pix/ amplifier	0.068 e-rms/pix
RNDR DEPFET	75 x 75 x 450	0.024 g	≈ 200 K	<u>≤ 1</u> e ⁻ /pix/day	4 μs/ 64 pix	0.2 e-rms/pix

similar concepts of non-destructive readout, compatible performance;
different architecture, different systematics;
-> good complementary from experimental point of view

DANAE proof-of-principle measurement

proto-type :
75 μm x 75 μm x 450 μm single pixel,
64 x 64 matrix
sensitive volume **0.024 g**

At HLL :

matrix readout

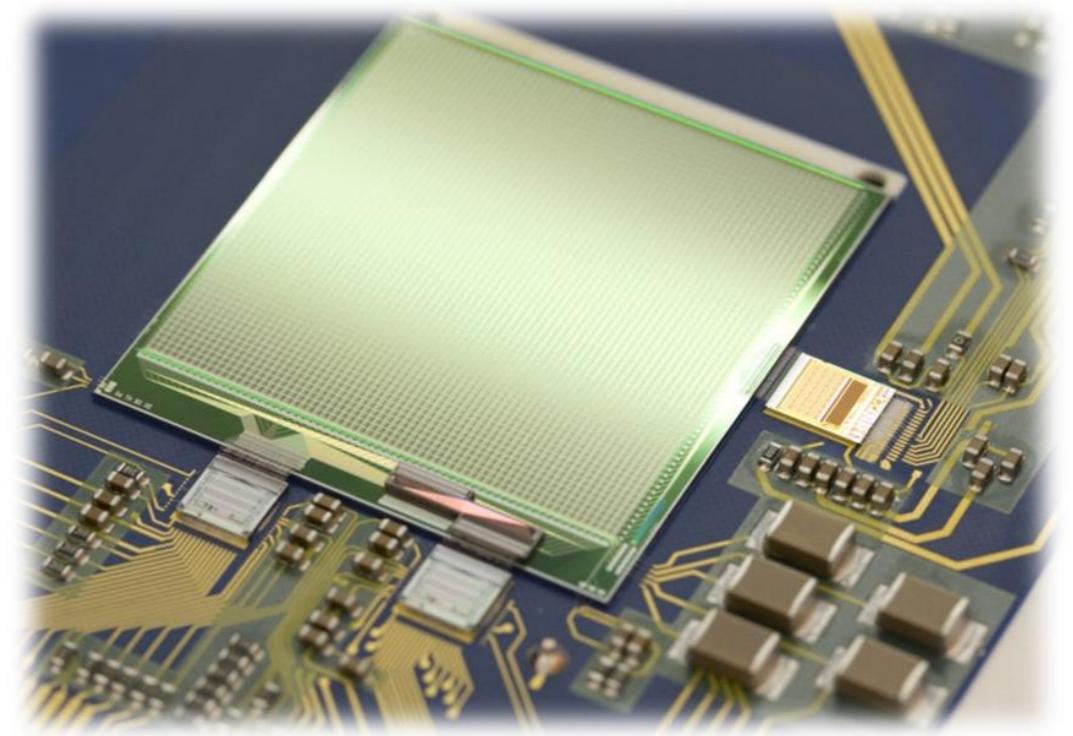
optimization for operational/readout parameters

temperature dependence of leakage current

In Vienna:

low background environment measurement
or surface measurement with veto

MC simulation for background budget

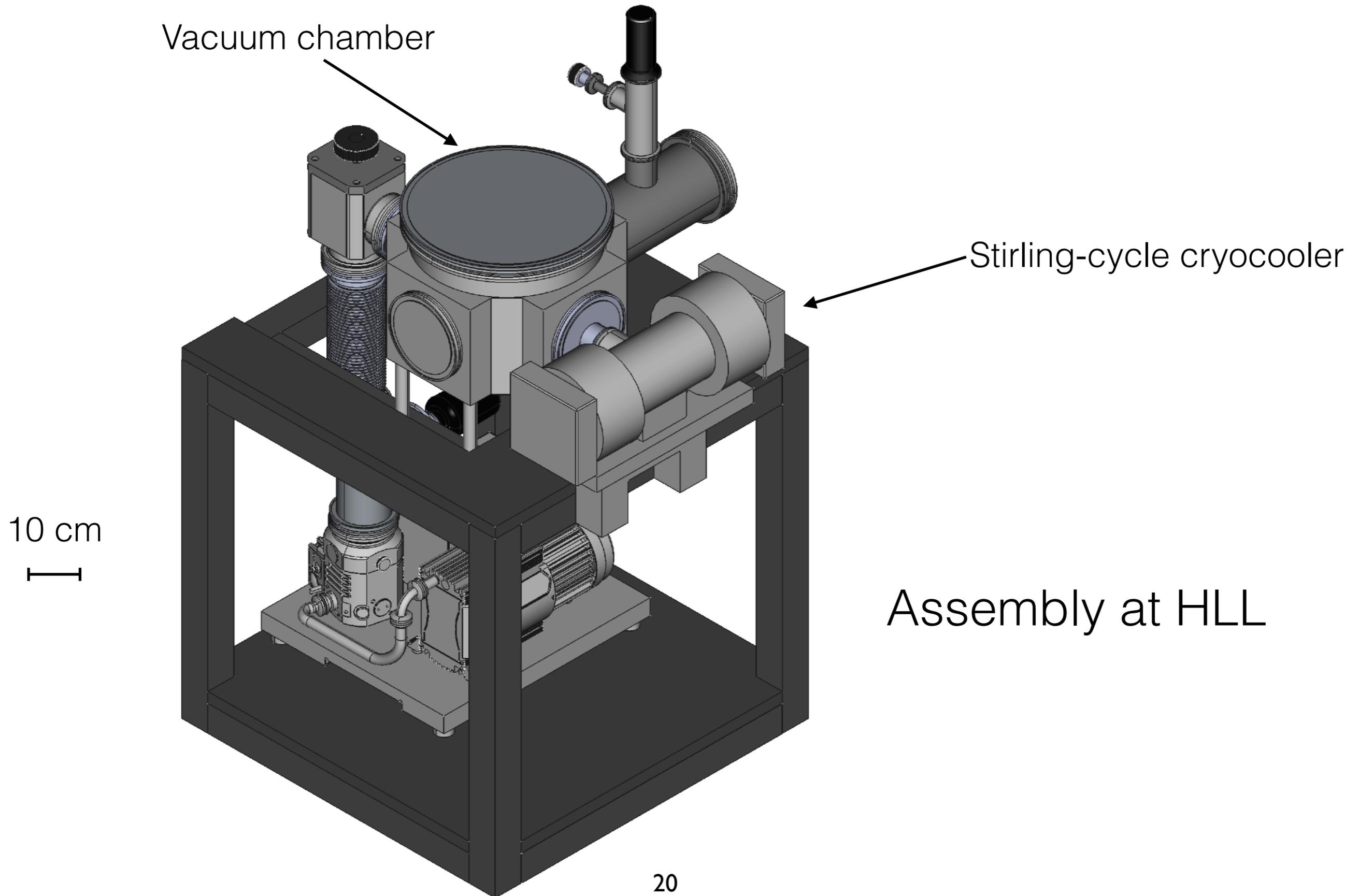


Detector prototype at HLL-MPG
courtesy of J. Treis

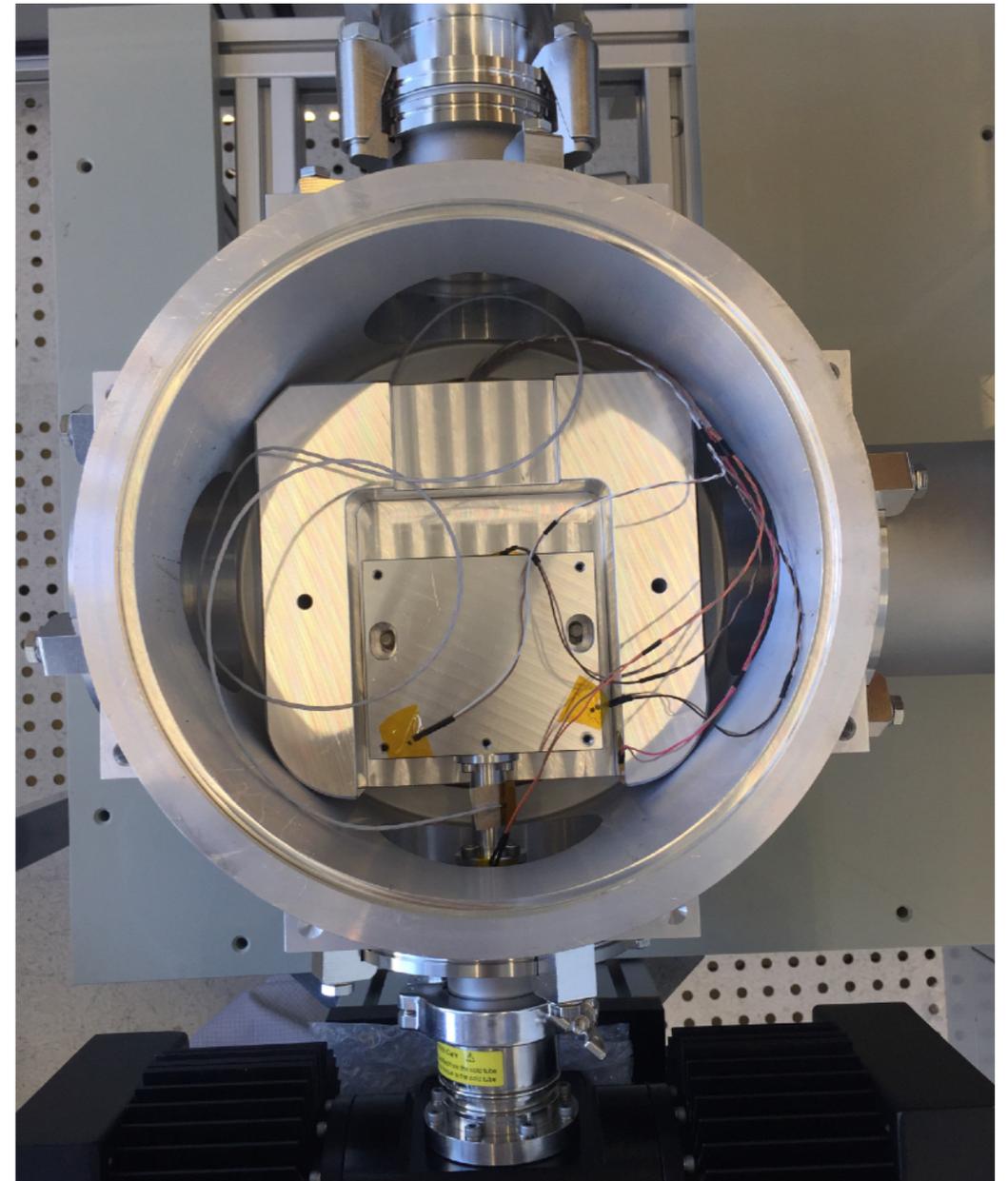
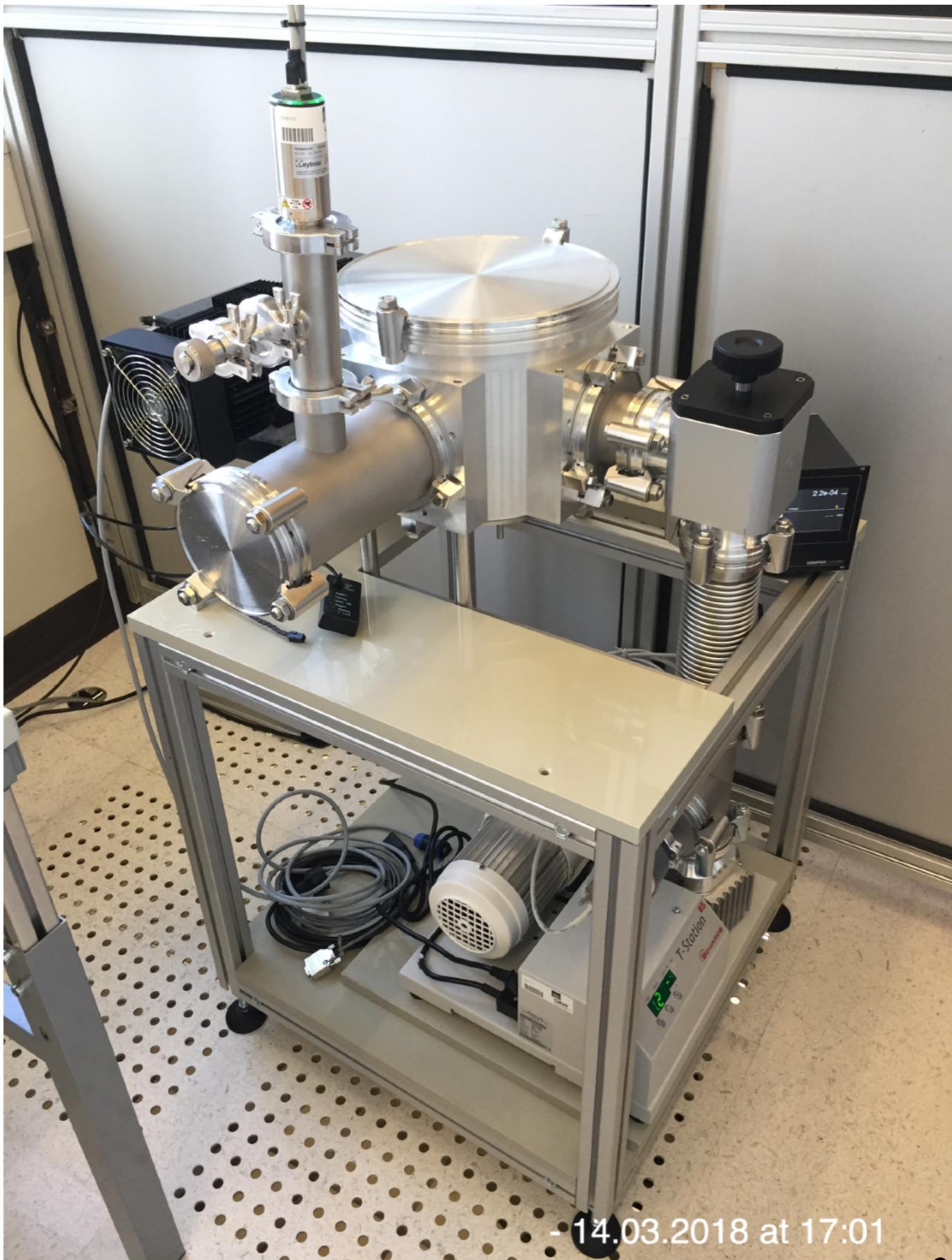
Expect to have operating
matrix by the end of 2018

DANAE preparation status

DANAE test setup - design image



Setup at HLL

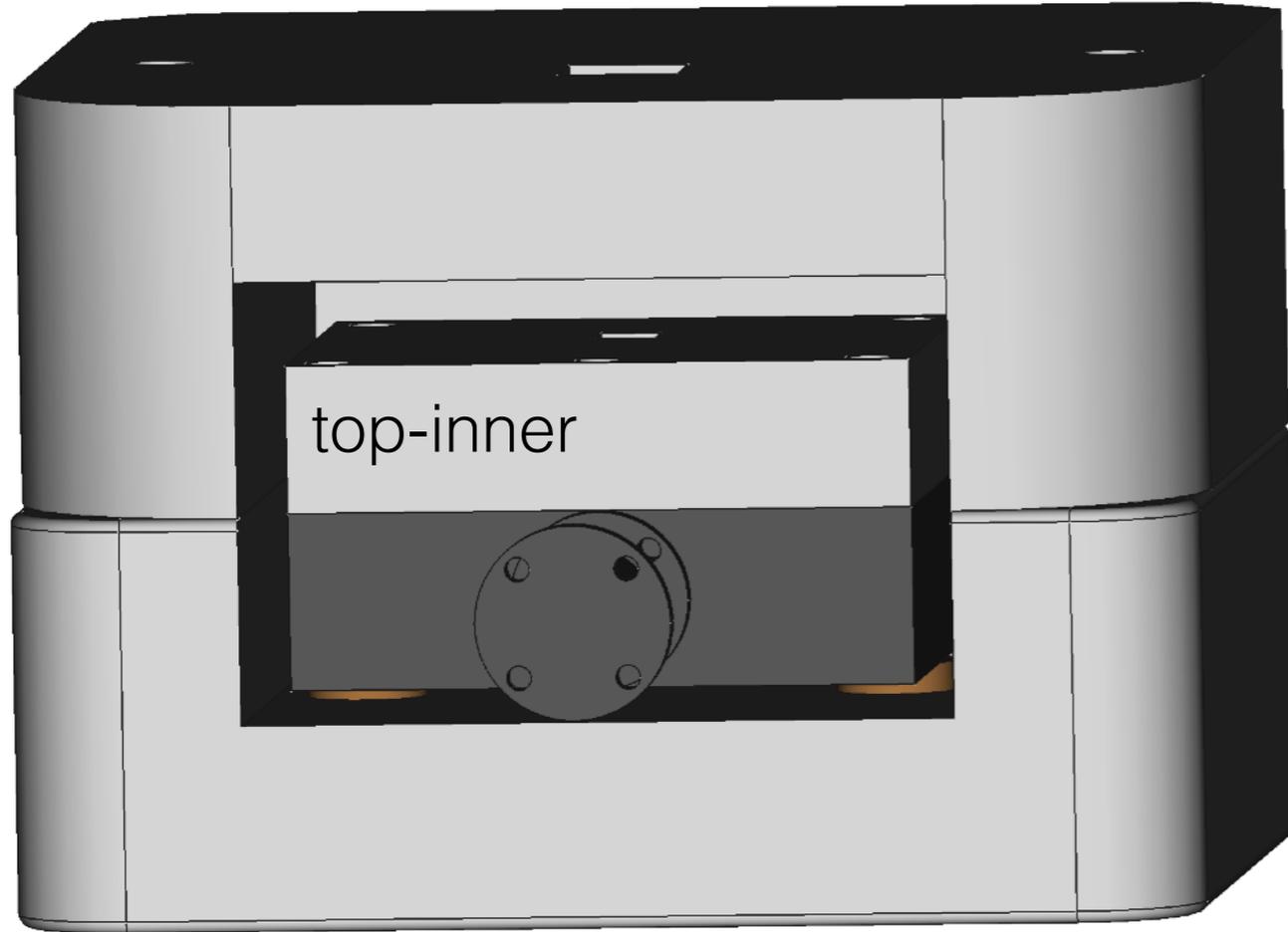


Vacuum and cooling tests
done in March 2018

cooling pad reached 150 K

Cooling & shielding layout

top-out



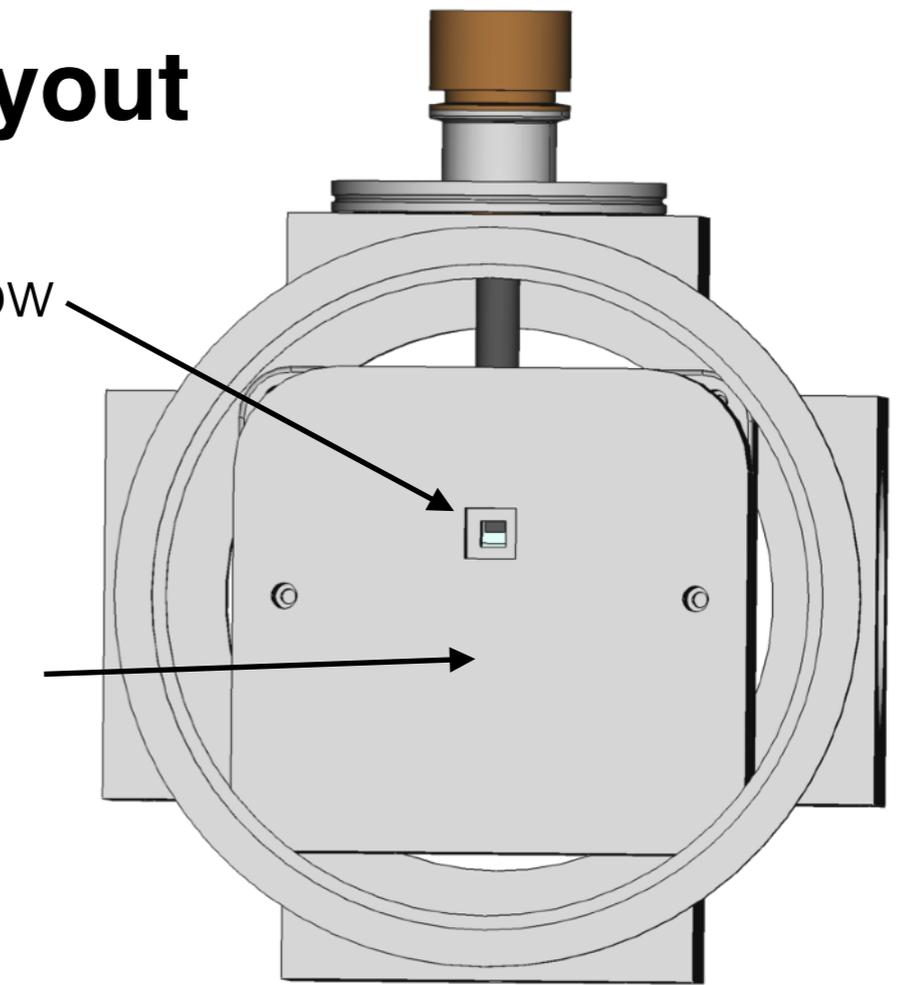
top-inner

bot-out

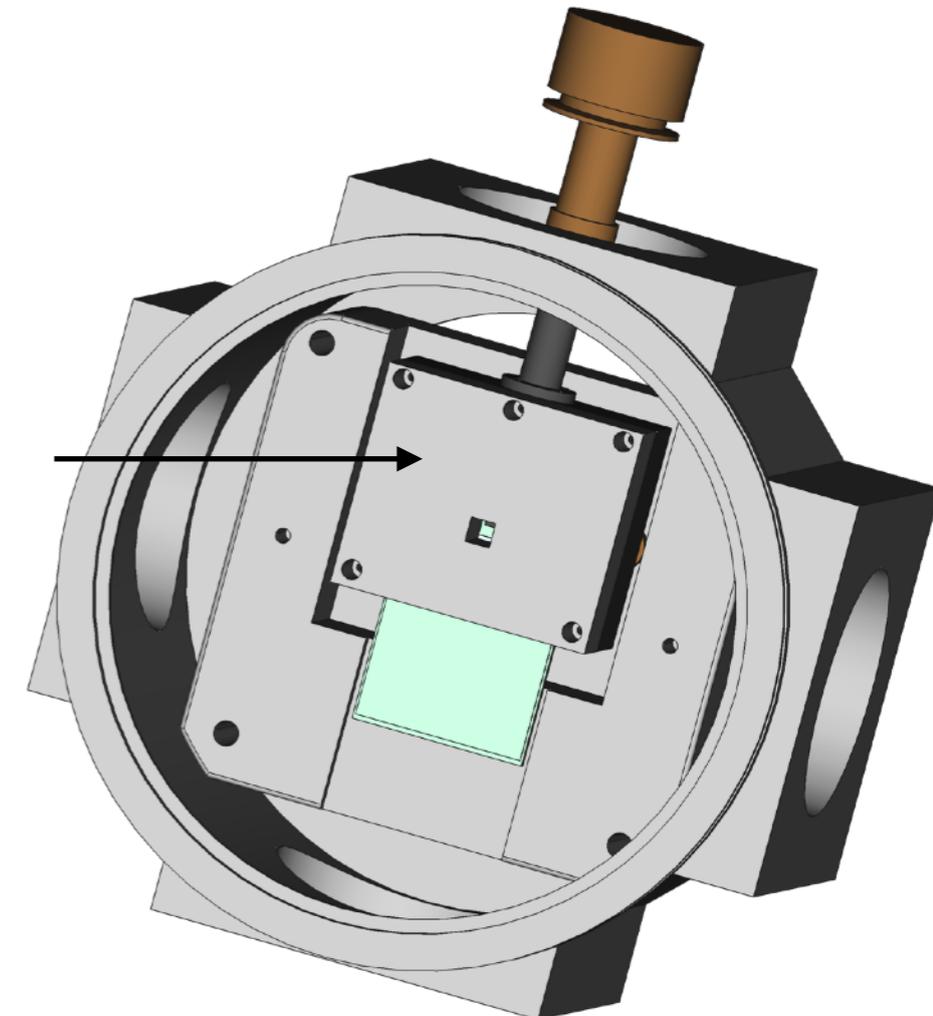
outer shielding : support structure
inner shielding : cooling contact

window

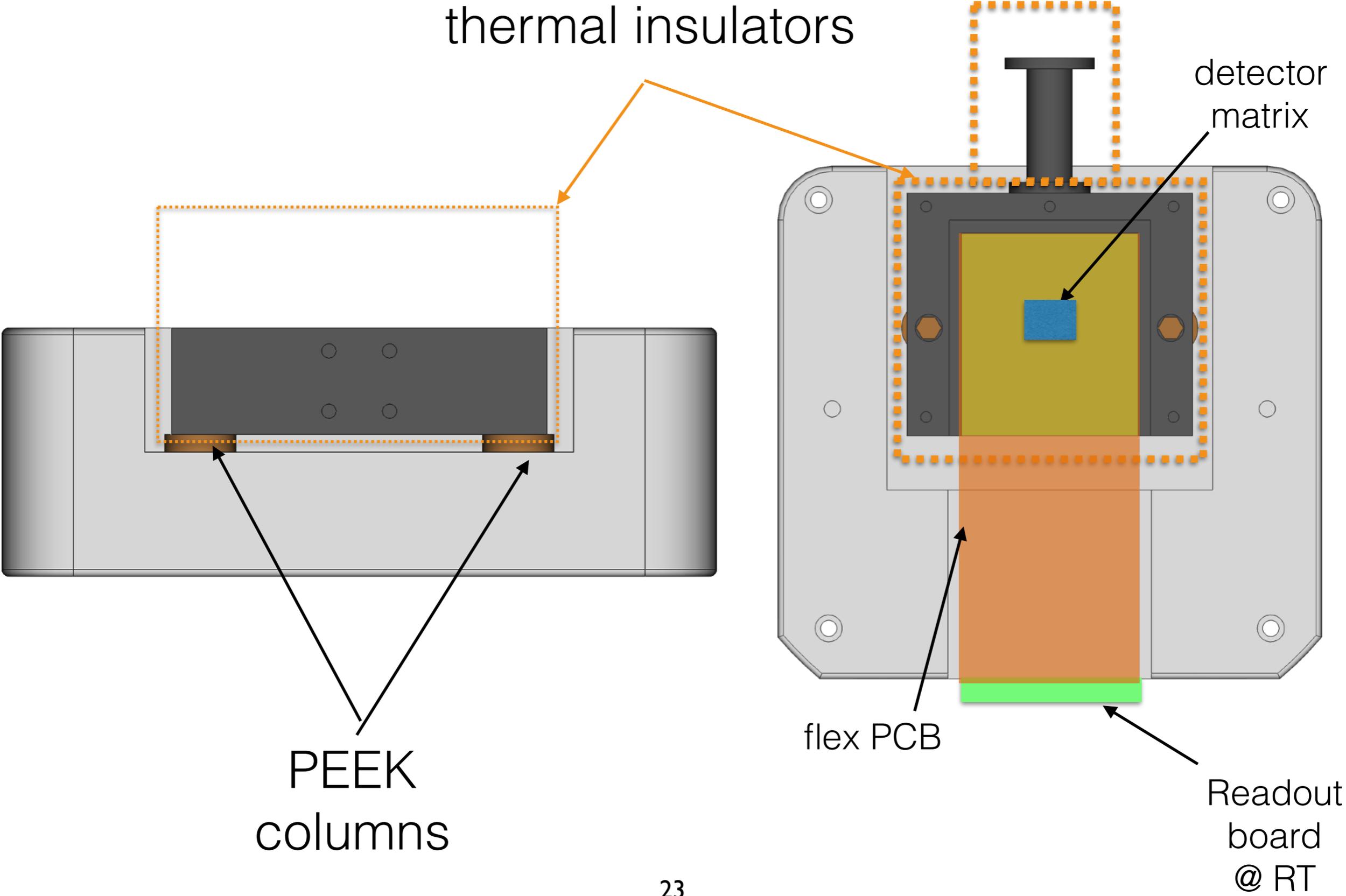
top out



top inner



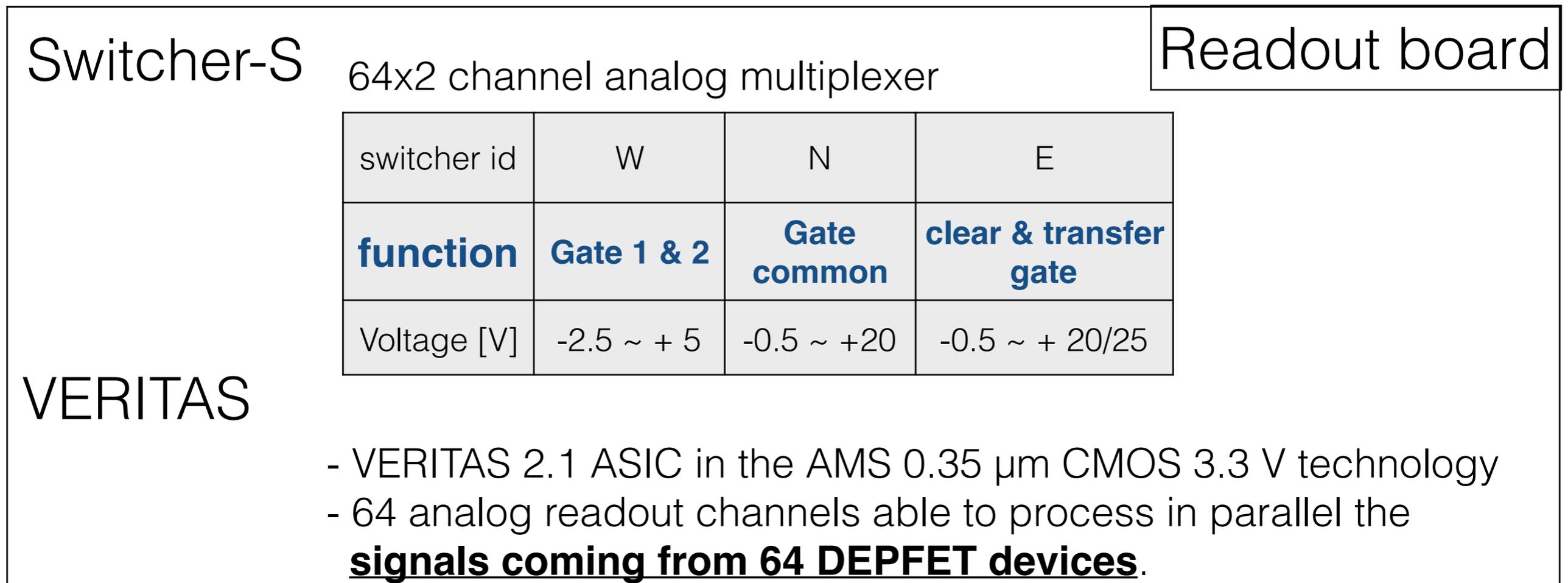
Cooling of the detector and electronics



DEPFET matrix control & readout electronics

Detector matrix

Front-end ASICS for the 64x64 matrix
with interface to Switcher-S, VERITAS



ADC

FADC type digitizer

DEPFET matrix control & readout electronics

Detector matrix

Front-end ASICS for the 64x64 matrix
with interface to Switcher-S, VERITAS

Switcher-S	64x2 channel analog multiplexer			Readout board
switcher id	W	N	E	
function	Gate 1 & 2	Gate common	clear & transfer gate	
Voltage [V]	-2.5 ~ + 5	-0.5 ~ +20	-0.5 ~ + 20/25	

VERITAS

- VERITAS 2.1 ASIC in the AMS 0.35 μm CMOS 3.3 V technology
- 64 analog readout channels able to process in parallel the **signals coming from 64 DEPFET devices.**

ADC

FADC type digitizer

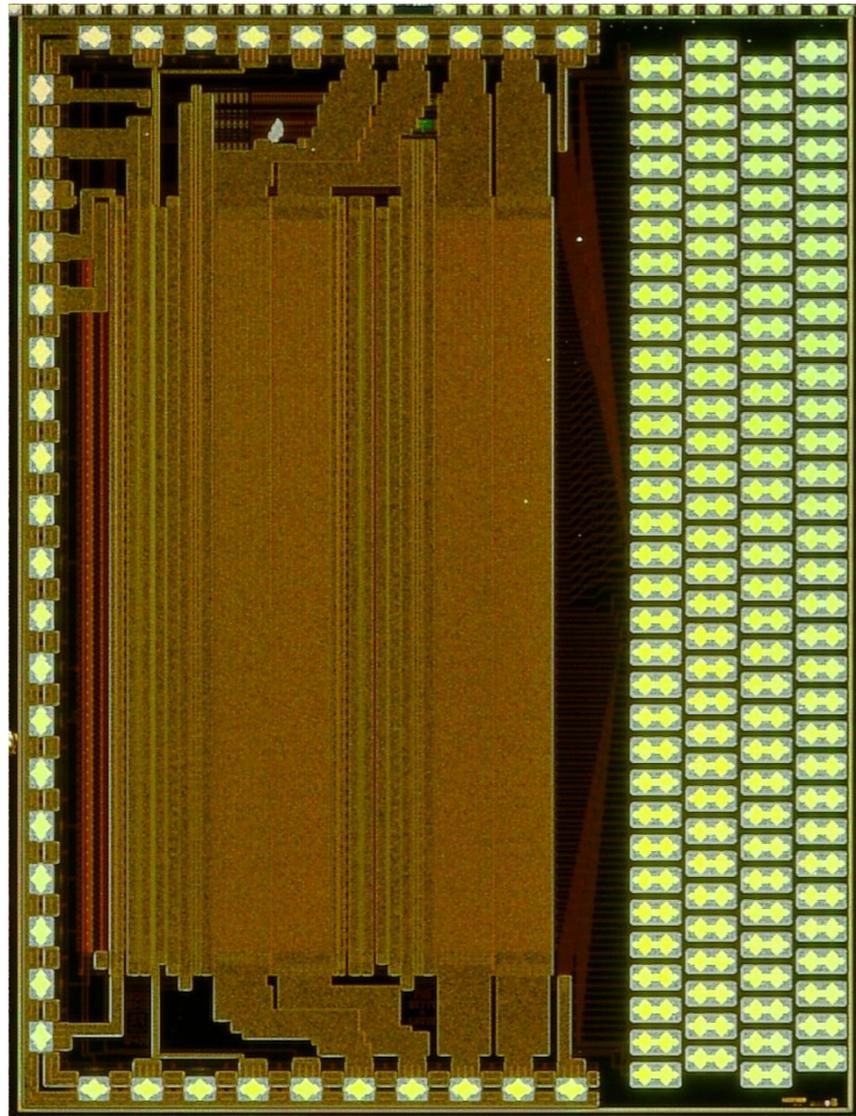
Switcher-S

Switcher-S, a HV Switch ASIC for DEPFET Matrix Control

Peter Fischer, STZ Microelectronics & Sensor Systems



Chip Manual, Version 3.2



64 x 2 channel analogue multiplexer ASIC for the row steering of DEPFET sensor matrices

for RNDR operation

- 3 chips
- programmable sequence

applications in BELLE DEPFET

DEPFET matrix control & readout electronics

Detector matrix

Front-end ASICS for the 64x64 matrix
with interface to Switcher-S, VERITAS

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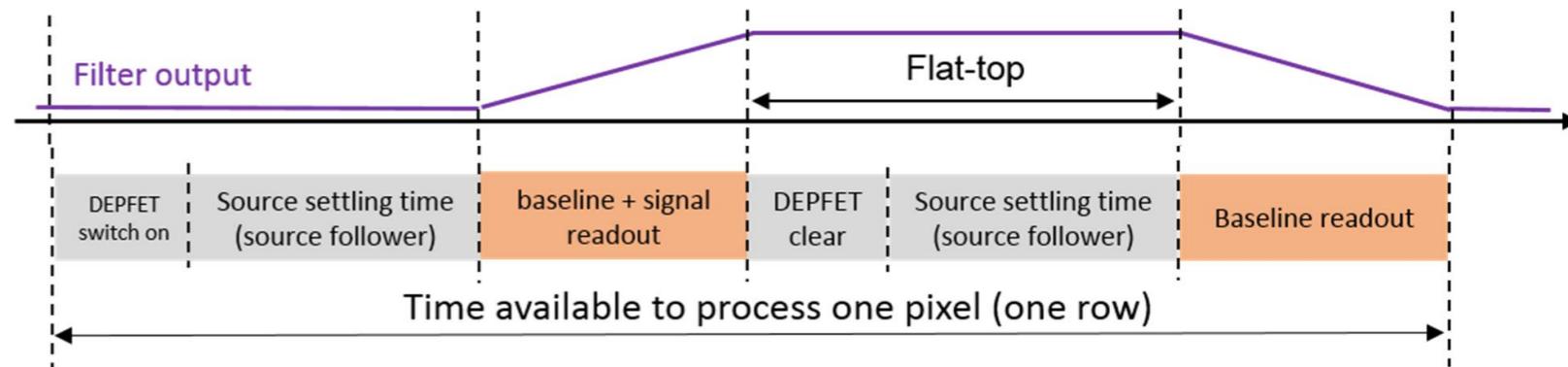
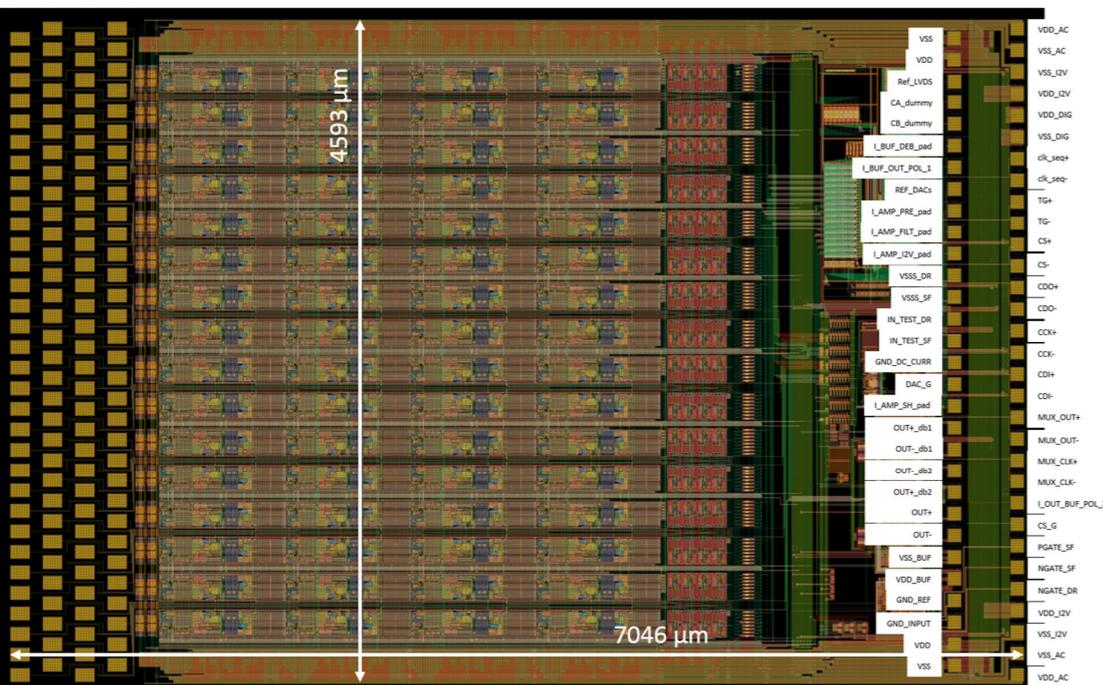
ADC

FADC type digitizer

VERITAS 2.1

- VERITAS 2.1 (Versatile Readout based on Integrated Trapezoidal Analog Shapers)
- 64-channel readout ASIC for DEPFET pixel arrays
- source-follower readout of DEPFET
- each channel implements a trapezoidal weighting function
- CDS : Correlated Double Sampling for signal

layout dimensions and pad stack
chip developed by MPE



time diagram of the filter operation with a trapezoidal weighting function

Correlated Double Sampling mode:

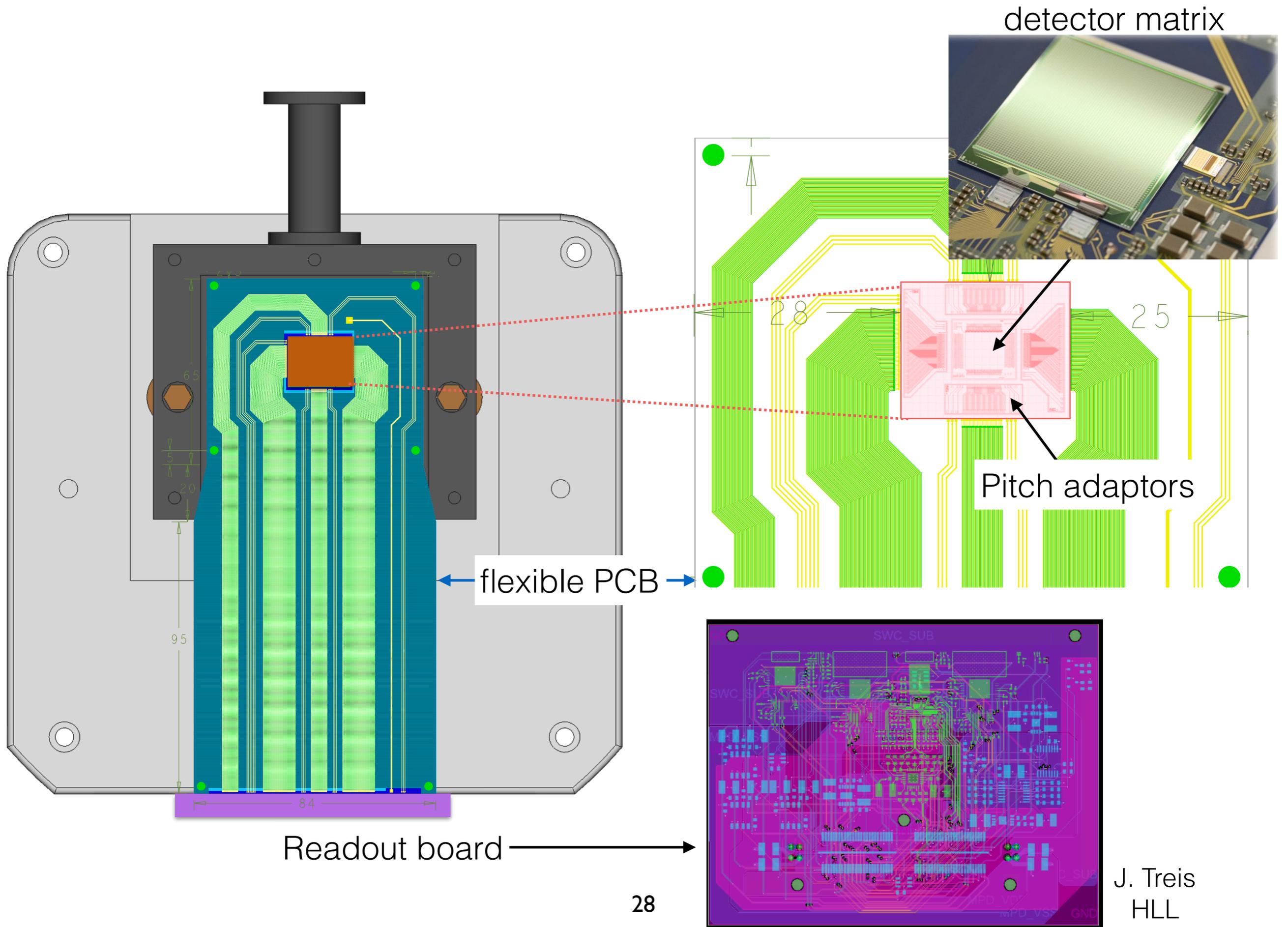
1st measurement : **baseline + signal**;

DEPFET CLEAR

2nd measurement : **baseline** ;

signal = difference

Detector control and readout electronics



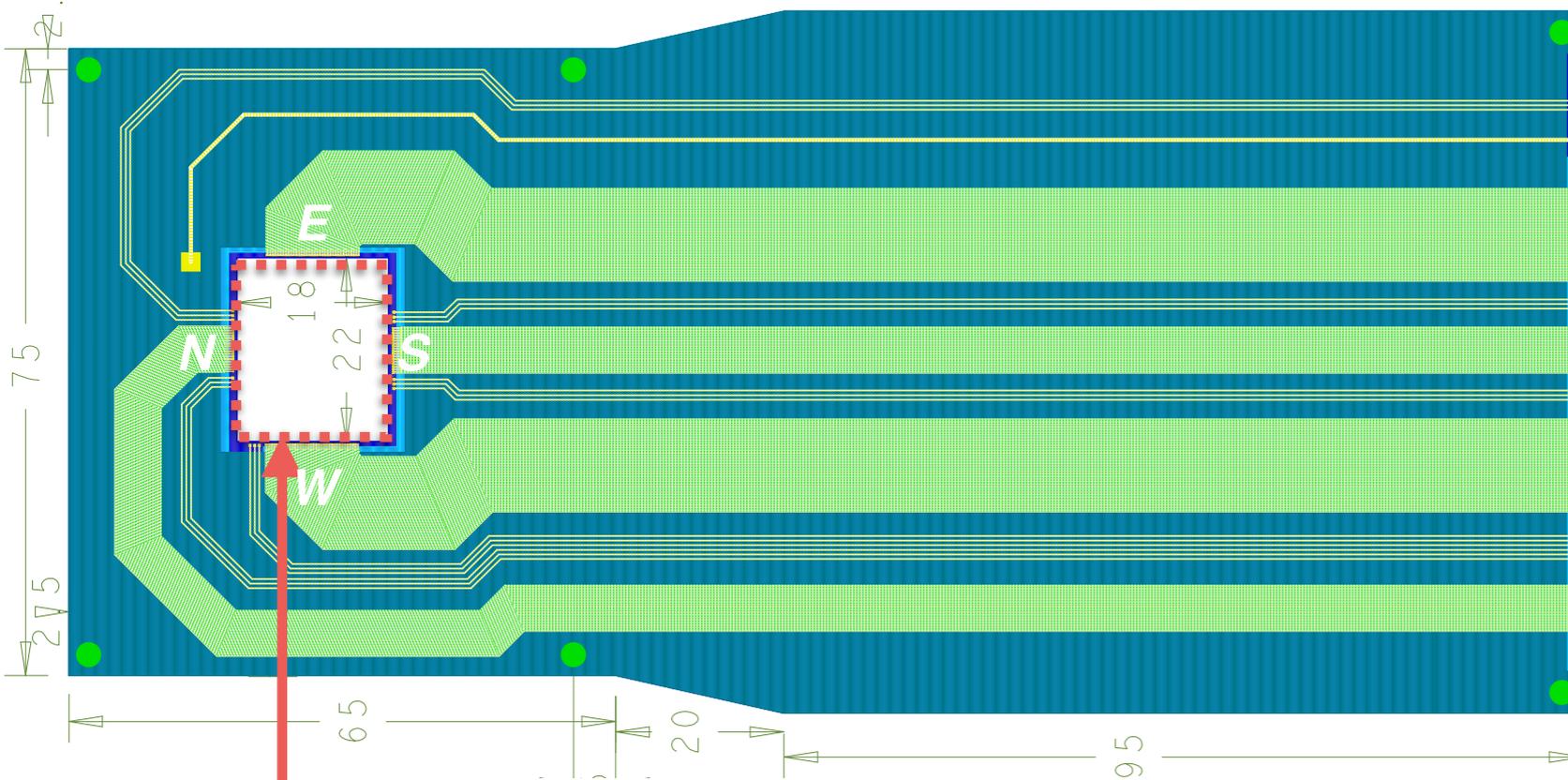
J. Treis
HLL

Readout PCB and Flex PCB

design using CADENCE 16.6
submitted to the manufactures

H. Shi
HEPHY

Flexible PCB



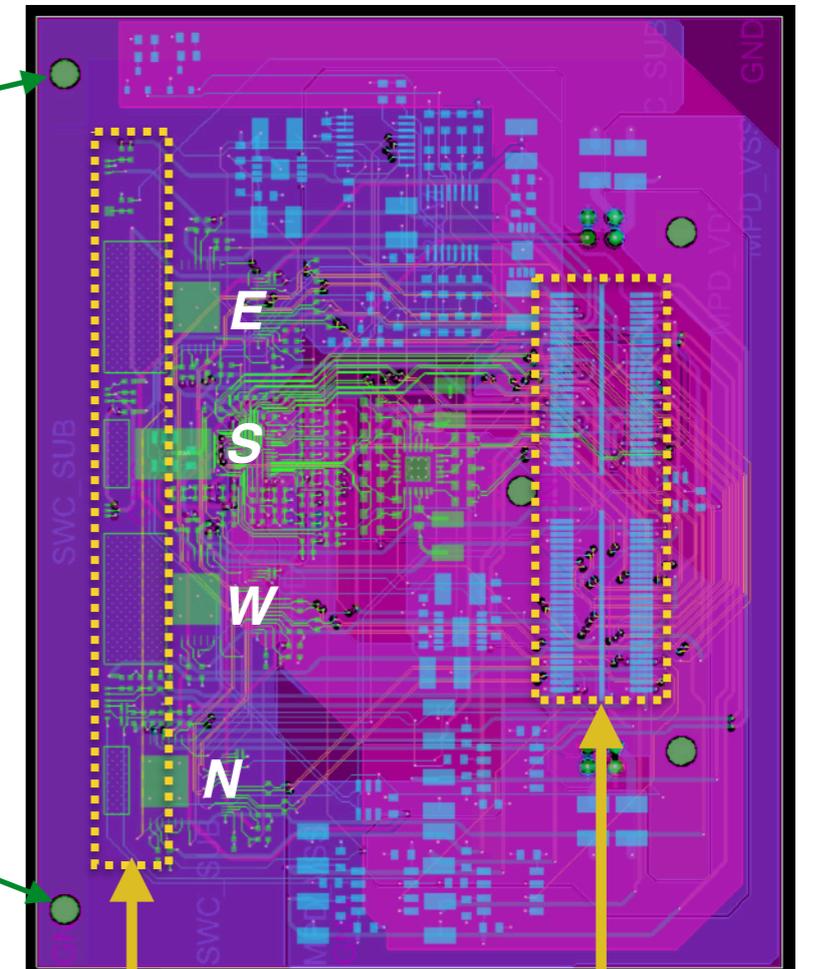
detector matrix

120 mm
flexible part

65 mm
glue to the ceramics

RO PCB

J. Treis
HLL

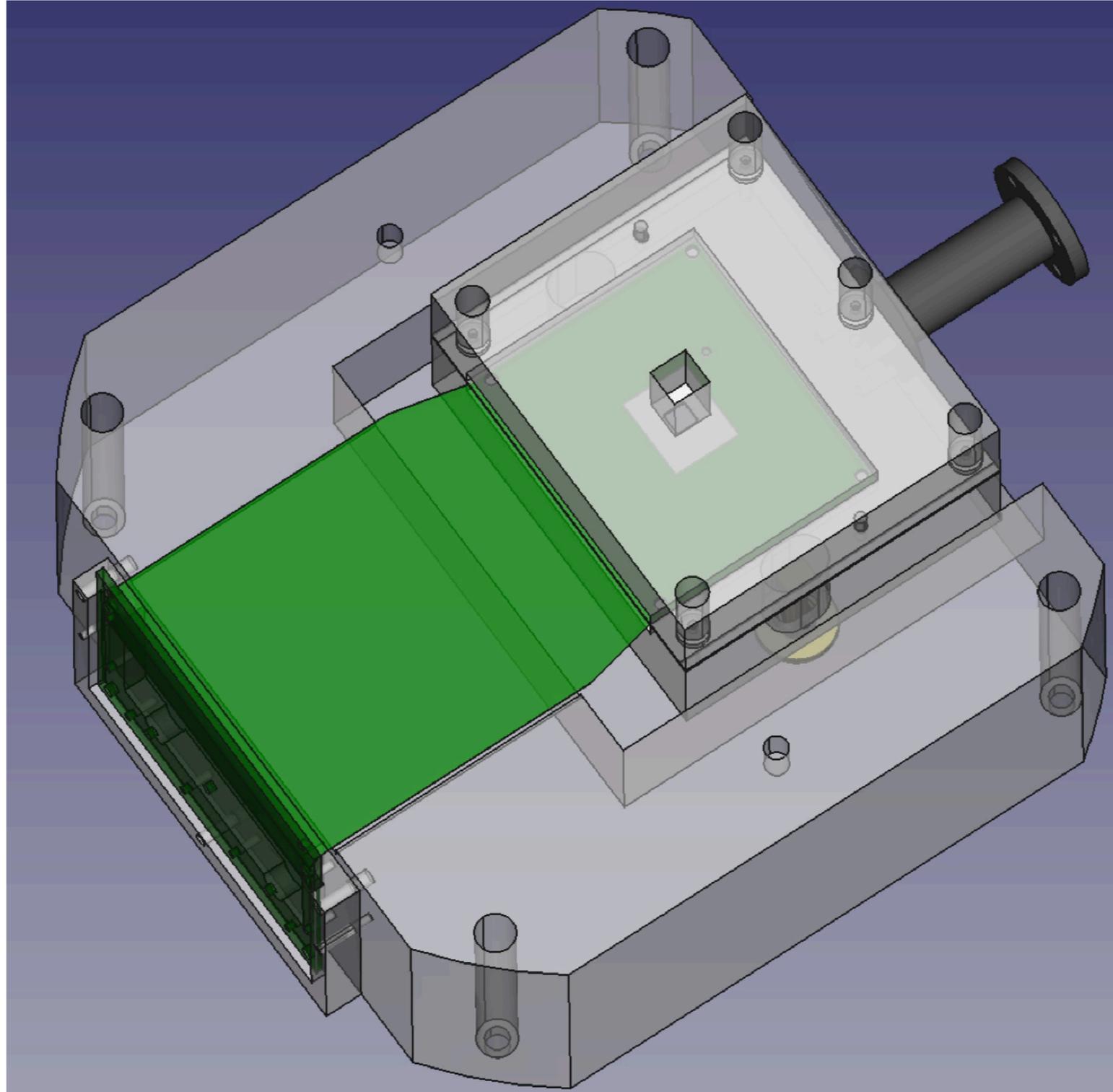


interface w flex
Al wire bonding

connector to
flange feedthrough

E, W, N : Switcher-S
S : VERITAS 2.1

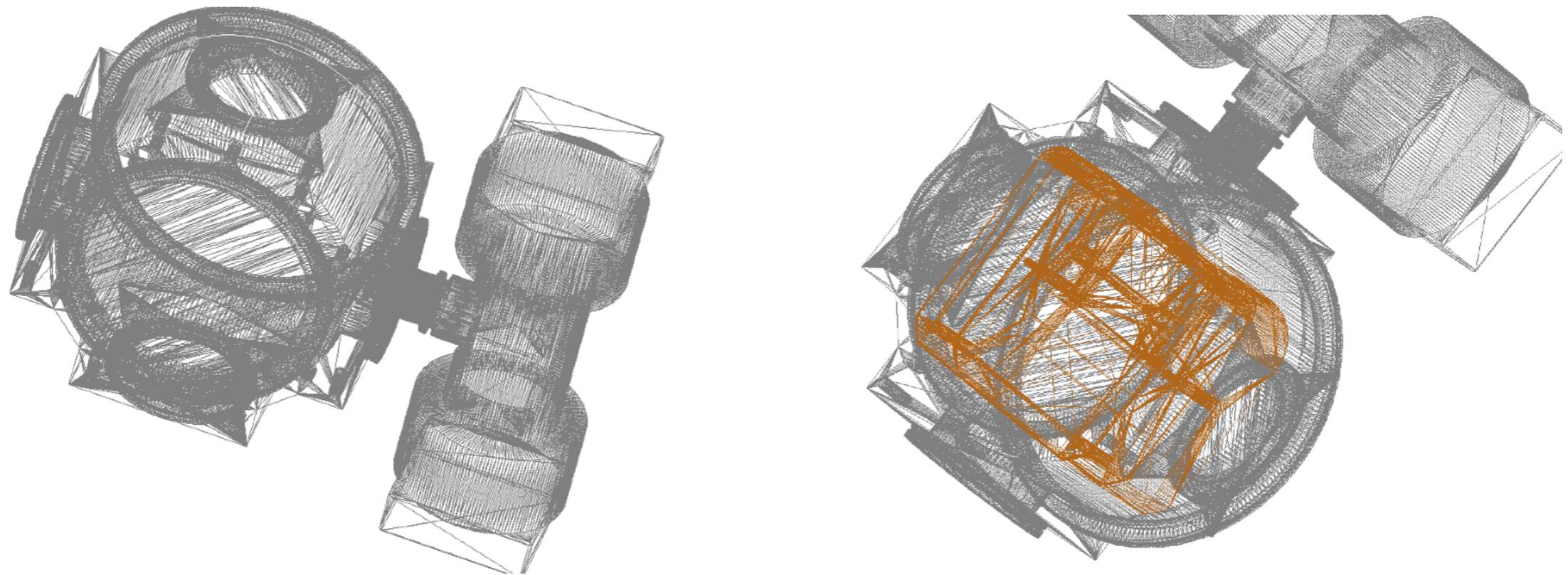
Image of the detector assembly



To be assembled in July-August 2018

Monte Carlo simulation with Geant4

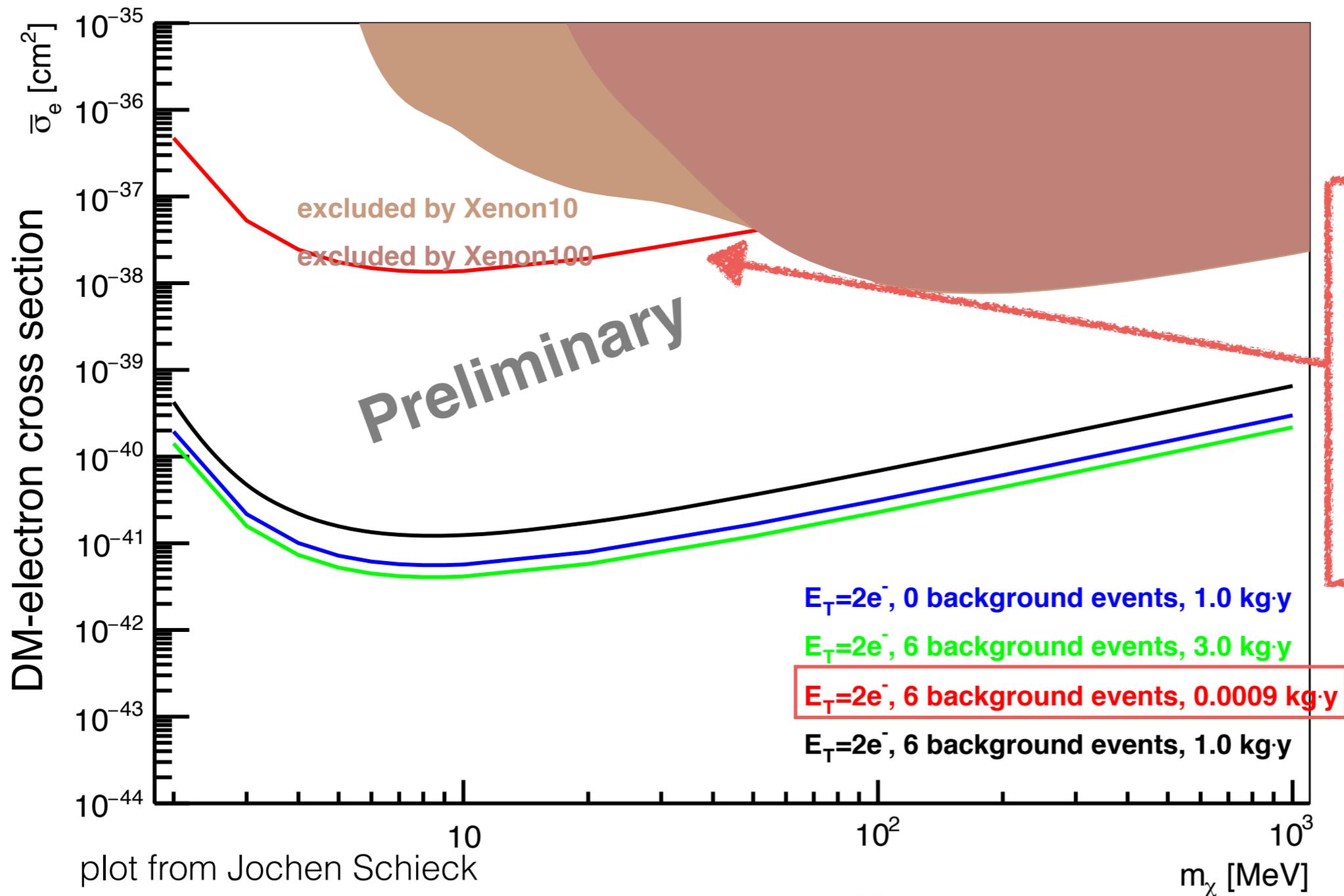
- to have a guideline of particle tracks and hit pattern, prepare the library of analysis routine;
- for future design of VETO counters and calibration layout.



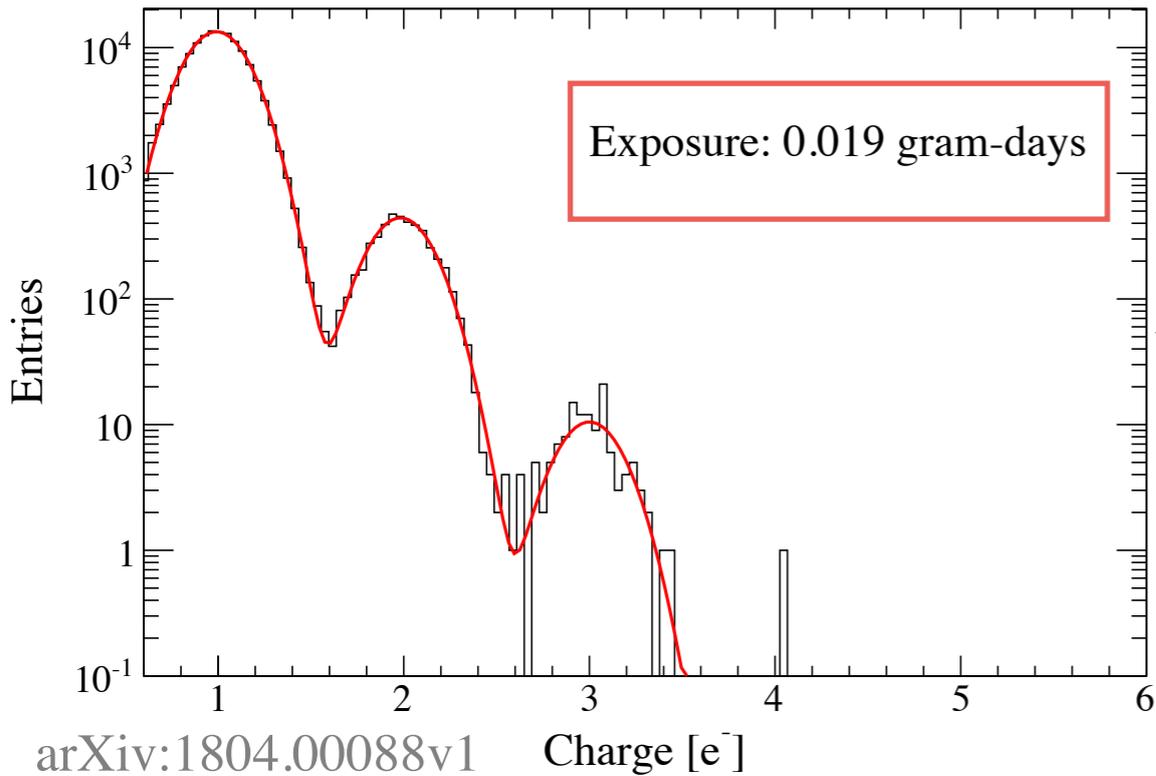
- geometry of the setup from vacuum parts 3D model;
- primitive geometrical shape for DEPFET :
 - 75 μm x 75 μm x 450 μm bulk pixel, 64 by 64 matrix;
- to check response to X-rays, ambient gamma, cosmic charged particles, and neutrons;

Physics run perspective

- Expect preliminary results from the prototype setup (0.024 g sensitive volume) in late 2018
- physics run with significant result requires more matrices

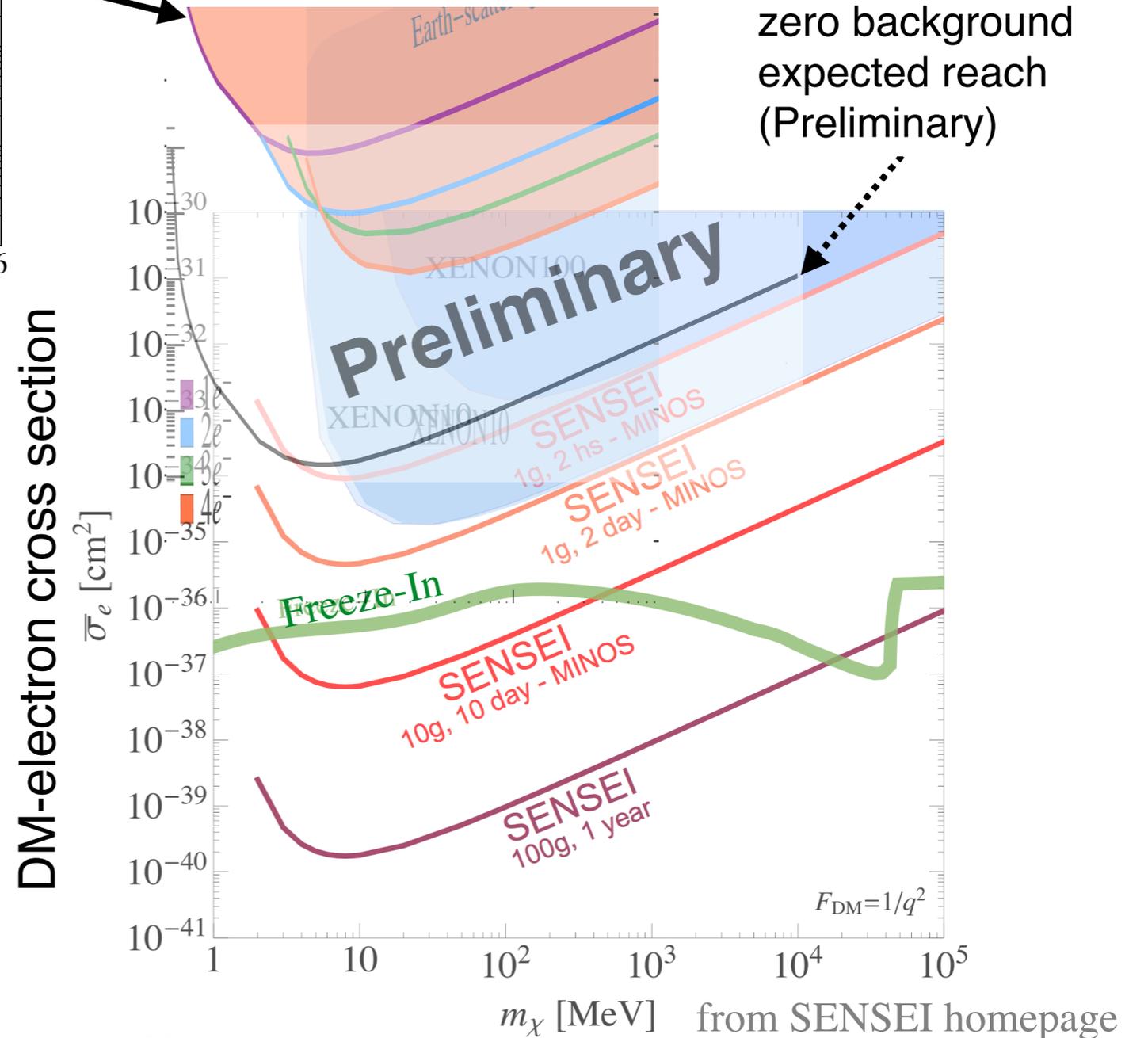


Expected 1day exposure compared to SENSEI



SENSEI prototype physics run

DANAЕ prototype 24 mg one-day exposure zero background expected reach (Preliminary)



Summary

- sub e^- ENC low noise semiconductor detector provides the possibility to detect the energy deposit from sub-GeV DM-electron recoil;
- DANAE prototype for test-of-principle measurement with single matrix in preparation;
- one of the first generation experiments using non-destructive repetitive readout method.

Future tasks & topics

- readout electronics production, DAQ;
- readout test, leakage current test;
- calibration regime and configuration;
- simulation for background budget;
- design for further shielding - passive and active.

Other topics for discussion

- connection/collaboration with VIP-2?
- VIP CCD data for DM search?
- possible application of low-noise detector

DANAE (DANAË)

Direct dArk matter search using DEPFET with repetitive- Non-destructive-readout Application Experiment

OeAW funding for detector technology



“Danae” by G. Klimt

Collaboration

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